



Intel® Stratix® 10 General Purpose I/O User Guide

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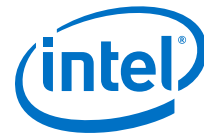


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1. Intel® Stratix® 10 I/O Overview

The Intel® Stratix® 10 general purpose I/O (GPIO) system consists of the I/O elements (IOE) and the GPIO Intel FPGA IP.

- The IOEs contain bidirectional I/O buffers and I/O registers located in LVDS I/O banks.
- The GPIO IP core supports the GPIO components and features, including double data rate I/O (DDIO), delay chains, I/O buffers, control signals, and clocking.
- Two of the LVDS I/O banks are shared with the Secure Device Manager (SDM).
- For devices with Hard Processor System (HPS), three of the LVDS I/O banks are shared with the HPS SDRAM interface.
- The 3 V I/O banks do not feature I/O registers and DDIOs.

Related Information

- [Secure Device Manager, Intel Stratix 10 Configuration User Guide](#)
Provides more information about the Secure Device Manager.
- [Restrictions on I/O Bank Usage for Intel Stratix 10 EMIF with HPS, Intel Stratix 10 External Memory Interfaces User Guide](#)
Provides more information about the shared LVDS I/O banks that are used by the HPS SDRAM interface.
- [Hard Processor System I/O Pin Multiplexing, Intel Stratix 10 Hard Processor System Technical Reference Manual](#)
Provides more information about the dedicated I/O pins in the HPS.
- [SDM Pin Mapping, Intel Stratix 10 Configuration User Guide](#)
Provides more information about pins in the SDM-shared LVDS I/O banks that are used by the SDM.
- [Secure Device Manager \(SDM\) Pins, Intel Stratix 10 GX, MX, and SX Device Family Pin Connection Guidelines](#)
Provides the descriptions and connection guidelines for the SDM pins.
- [HyperFlex Core Architecture, Intel Stratix 10 Device Overview](#)
Provides more information about Hyper-Registers and the HyperFlex core architecture. Hyper-Registers are additional registers available in every interconnect routing segment throughout the core fabric, including the routing segments connected to the I/O buffer inputs and outputs.
- [Intel Stratix 10 General Purpose I/O User Guide Archives](#) on page 63
Provides a list of user guides for previous versions of the GPIO Intel FPGA IP.



1.1. Intel Stratix 10 I/O and Differential I/O Buffers

The general purpose I/Os (GPIOs) consist of LVDS I/O and 3 V I/O banks:

- LVDS I/O bank—supports differential and single-ended I/O standards up to 1.8 V. The LVDS I/O pins form pairs of true differential LVDS channels. Each pair supports a parallel input/output termination between the two pins. You can use each LVDS channel as transmitter only or receiver only. Each LVDS channel supports transmit SERDES and receive SERDES with DPA circuitry. For example, if you use 30 channels of the available 72 channels as transmitters, you can use the remaining 42 channels as receivers.
- 3 V I/O bank—supports single-ended and differential SSTL, HSTL, and HSUL I/O standards up to 3 V. In Intel Stratix 10 devices, each 3 V I/O bank supports only two output enables (OE) for its eight single-ended I/Os. Single-ended I/O within this I/O bank support all programmable I/O element (IOE) features except:
 - Programmable pre-emphasis
 - R_D on-chip termination (OCT)
 - Calibrated R_S and R_T OCT
 - Internal V_{REF} generation
 - Dynamic OCT

Note: The 3 V I/O banks in Intel Stratix 10 devices do not support the DDIO feature of the GPIO IP core. Bypass the DDIO if you use an I/O standard supported only by 3 V I/O banks, such as 3.0 V LVCMOS. To bypass the DDIO feature, set the **Register mode** of the GPIO IP core to **none**.

Note: The 3 V I/O banks are located on the Intel Stratix 10 transceiver tiles. These banks are available only on the L-tile and H-tile transceiver tiles.

Related Information

- [Programmable IOE Features in Intel Stratix 10 Devices](#) on page 13
- [Pin-Out Files for Intel Stratix 10 Devices](#)
Provides the I/O counts and I/O bank locations for each Intel Stratix 10 device and package.



1.2. Intel Stratix 10 I/O Vertical Migration Support

Figure 1. Migration Capability Across Intel Stratix 10 Product Lines—Preliminary

- The arrows indicate the migration paths. The devices included in each vertical migration path are shaded. Devices with fewer resources in the same path have lighter shades.
- To achieve the full I/O migration across product lines in the same migration path, restrict I/Os and transceivers usage to match the product line with the lowest I/O and transceiver counts.
- You can migrate horizontally between the UF53 and NF53 packages of the Intel Stratix 10 MX 2100 product line. However, different ordering part number of the product line has different LE count or HBM features.

| Variant | Product Line | Package | | | | | | | | | |
|---------------|--------------|---------|------|------|------|------|------|------|------|------|------|
| | | HF35 | NF43 | NF48 | SF48 | UF50 | UF53 | NF53 | HF55 | YF55 | UF55 |
| Stratix 10 GX | GX 400 | ↑↓ | | | | | | | | | |
| | GX 650 | ↓ | | | | | | | | | |
| | GX 850 | | ↑ | ↑↓ | | | | | | | |
| | GX 1100 | | | ↓ | | | | | | | |
| | GX 1650 | | | | | ↑ | | | | | |
| | GX 2100 | | | | | ↓ | | | | | |
| | GX 2500 | | | | | | | | ↑ | | |
| | GX 2800 | | | | | | | | ↓ | | |
| | GX 5500 | | | | | | | | | ↑↓ | |
| Stratix 10 TX | TX 1650 | | | | ↑ | ↑ | | | | | |
| | TX 2100 | | | | ↓ | ↓ | | | | | |
| | TX 2500 | | | | | | | | ↑ | | |
| | TX 2800 | | | | | | | | ↓ | | |
| Stratix 10 MX | MX 1100 | | | | | | | | | | |
| | MX 1650 | | | | | | | | | | |
| | MX 2100 | | | | | | ← | → | | ↑↓ | |
| Stratix 10 SX | SX 400 | ↑↓ | | | | | | | | | |
| | SX 650 | ↓ | | | | | | | | | |
| | SX 850 | | ↑ | ↑↓ | | | | | | | |
| | SX 1100 | | | ↓ | | | | | | | |
| | SX 1650 | | | | | ↑ | | | | | |
| | SX 2100 | | | | | ↓ | | | | | |
| | SX 2500 | | | | | | | | ↑ | | |
| | SX 2800 | | | | | | | | ↓ | | |
| | SX 4500 | | | | | | | | | ↑↓ | |
| SX 5500 | | | | | | | | | | | |

Note: To verify the pin migration compatibility, use the **Pin Migration View** window in the Intel Quartus® Prime software Pin Planner.

2. Intel Stratix 10 I/O Architecture and Features

The I/O system of Intel Stratix 10 devices support various I/O standards. In the Intel Stratix 10 devices, the I/O pins are located in I/O banks. The I/O pins and I/O buffers have several programmable features.

The Intel Stratix 10 I/Os support the following features:

- Single-ended, non-voltage-referenced, and voltage-referenced I/O standards
- Low-voltage differential signaling (LVDS), RSDS, mini-LVDS, HSTL, HSUL, SSTL, and POD I/O standards
- Serializer/deserializer (SERDES)
- Programmable output current strength
- Programmable slew rate
- Programmable bus-hold
- Programmable weak pull-up resistor
- Programmable pre-emphasis for DDR4 and the LVDS output buffer
- Programmable I/O delay
- Programmable differential output voltage (V_{OD})
- Programmable open-drain output
- On-chip series termination (R_S OCT) with and without calibration
- On-chip parallel termination (R_T OCT)
- On-chip differential termination (R_D OCT)
- HSTL and SSTL input buffer with dynamic power down
- Dynamic on-chip parallel termination for all I/O banks
- Internally generated V_{REF} with DDR4 calibration

Note: The information in this chapter is applicable to all Intel Stratix 10 variants, unless noted otherwise.

2.1. I/O Standards and Voltage Levels in Intel Stratix 10 Devices

The Intel Stratix 10 device family consists of FPGA and SoC devices. The Intel Stratix 10 FPGA devices have only FPGA I/O buffers. The Intel Stratix 10 SoC devices have FPGA I/O and HPS I/O buffers. The HPS I/O buffers in Intel Stratix 10 SoC devices support different I/O standards than the FPGA I/O buffers.



2.1.1. Intel Stratix 10 I/O Standards Support

Table 1. Intel Stratix 10 Devices I/O Standards Support for FPGA I/O—Preliminary

| I/O Standard | I/O Buffer Type Support | | Application | Standard Support |
|---|-------------------------|---------------------------|--|------------------|
| | LVDS I/O | 3 V I/O ⁽¹⁾⁽²⁾ | | |
| 3.0 V LVTTTL/3.0 V LVCMOS | No | Yes | General purpose | JESD8-B |
| 2.5 V LVCMOS | No | Yes ⁽³⁾ | General purpose | JESD8-5 |
| 1.8 V LVCMOS | Yes | Yes ⁽³⁾ | General purpose | JESD8-7 |
| 1.5 V LVCMOS | Yes | Yes ⁽³⁾ | General purpose | JESD8-11 |
| 1.2 V LVCMOS | Yes | Yes ⁽³⁾ | General purpose | JESD8-12 |
| SSTL-18 Class I and Class II | Yes | No | Flash interface | JESD8-15 |
| SSTL-15 Class I and Class II | Yes | No | DDR3 | — |
| SSTL-15 | Yes | No | DDR3 | JESD79-3D |
| SSTL-135 | Yes | No | DDR3L | — |
| SSTL-125 ⁽⁴⁾ | Yes | No | QDR-IV | — |
| SSTL-12 | Yes | No | RLDRAM 3, QDR-IV | — |
| POD12 | Yes | No | DDR4, QDR-IV | JESD8-24 |
| 1.8 V HSTL Class I and Class II | Yes | No | DDR II+, QDR II+, and RLDRAM 2 | JESD8-6 |
| 1.5 V HSTL Class I and Class II | Yes | No | DDR II+, QDR II+, QDR II, and RLDRAM 2 | JESD8-6 |
| 1.2 V HSTL Class I and Class II | Yes | No | QDR-IV, General purpose | JESD8-16A |
| HSUL-12 | Yes | No | LPDDR2, LPDDR3 | — |
| Differential SSTL-18 Class I and Class II | Yes | No | General purpose | JESD8-15 |
| Differential SSTL-15 Class I and Class II | Yes | No | DDR3 | — |
| Differential SSTL-15 | Yes | No | DDR3 | JESD79-3D |
| Differential SSTL-135 | Yes | No | DDR3L | — |
| Differential SSTL-125 ⁽⁴⁾ | Yes | No | General purpose | — |
| Differential SSTL-12 | Yes | No | RLDRAM 3 | — |
| Differential POD12 | Yes | No | DDR4 | JESD8-24 |

continued...

- (1) Available only on L-tile and H-tile transceiver tiles.
- (2) When a transceiver tile is powered down, the tile's 3 V I/O bank is not available.
- (3) You must set the `USE_AS_3V_GPIO` Intel Quartus Prime assignment to the pin.
- (4) Even though the Intel Stratix 10 I/O buffers support various I/O standards for memory application, Intel validates and support only IPs for memory interfaces listed in [Performance Support Summary, Intel Stratix 10 External Memory Interfaces User Guide](#).



| I/O Standard | I/O Buffer Type Support | | Application | Standard Support |
|--|-------------------------|---------------------------|---|------------------|
| | LVDS I/O | 3 V I/O ⁽¹⁾⁽²⁾ | | |
| Differential 1.8 V HSTL Class I and Class II | Yes | No | DDR II+, QDR II+, and RLD RAM 2 | JESD8-6 |
| Differential 1.5 V HSTL Class I and Class II | Yes | No | DDR II+, QDR II+, QDR II, and RLD RAM 2 | JESD8-6 |
| Differential 1.2 V HSTL Class I and Class II | Yes | No | General purpose | JESD8-16A |
| Differential HSUL-12 | Yes | No | LPDDR2, LPDDR3 | — |
| LVDS | Yes | No | SGMII, SFI, SPI | ANSI/TIA/EIA-644 |
| Mini-LVDS | Yes | No | SGMII, SFI, SPI | — |
| RSDS | Yes | No | SGMII, SFI, SPI | — |
| LVPECL | Yes | No | SGMII, SFI, SPI | — |

Note: To use the 1.2 V, 1.5 V, 1.8 V, or 2.5 V I/O standards in the 3 V I/O bank, you must set the **USE_AS_3V_GPIO** assignment to the I/O pin. In the Intel Quartus Prime Settings File (.qsf), specify the following assignment: `set_instance_assignment -name USE_AS_3V_GPIO ON -to <your pin name>`

Table 2. Intel Stratix 10 SX Devices I/O Standards Support for HPS I/O—Preliminary

| I/O Standard | Application | Standard Support |
|--------------|-----------------|------------------|
| 1.8 V LVCMOS | General purpose | JESD8-7 |

2.1.2. Intel Stratix 10 I/O Standards Voltage Support

Intel Stratix 10 devices in all packages can interface with systems of different supply voltages.

- The I/O buffers are powered by V_{CC} , V_{CCPT} and V_{CCIO} .
- Each I/O bank has its own V_{CCIO} supply and supports only one V_{CCIO} voltage.
- In all I/O banks, you can use any of the listed V_{CCIO} voltages except 2.5 V and 3.0 V.
- The 2.5 V and 3.0 V V_{CCIO} voltages are supported only on the 3 V I/O banks.
- For the maximum and minimum input voltages allowed, refer to the device datasheet.

(1) Available only on L-tile and H-tile transceiver tiles.

(2) When a transceiver tile is powered down, the tile's 3 V I/O bank is not available.



Table 3. Intel Stratix 10 Devices I/O Standards Voltage Levels

This table lists the typical power supplies for each supported I/O standards in Intel Stratix 10 devices.

| I/O Standard | V _{CCIO} (V) | | V _{CCPT} (V) (Pre-Driver Voltage) | V _{REF} (V) (Input Ref Voltage) | V _{TT} (V) (Board Termination Voltage) |
|--|-----------------------|--------|---|---|--|
| | Input ⁽⁵⁾ | Output | | | |
| 3.0 V LVTTTL/3.0 V LVCMOS | 3.0 | 3.0 | 1.8 | — | — |
| 2.5 V LVCMOS | 3.0/2.5 | 2.5 | 1.8 | — | — |
| 1.8 V LVCMOS | 1.8 | 1.8 | 1.8 | — | — |
| 1.5 V LVCMOS | 1.5 | 1.5 | 1.8 | — | — |
| 1.2 V LVCMOS | 1.2 | 1.2 | 1.8 | — | — |
| SSTL-18 Class I and Class II | V _{CCPT} | 1.8 | 1.8 | 0.9 | 0.9 |
| SSTL-15 Class I and Class II | V _{CCPT} | 1.5 | 1.8 | 0.75 | 0.75 |
| SSTL-15 | V _{CCPT} | 1.5 | 1.8 | 0.75 | 0.75 |
| SSTL-135 | V _{CCPT} | 1.35 | 1.8 | 0.675 | 0.675 |
| SSTL-125 | V _{CCPT} | 1.25 | 1.8 | 0.625 | 0.625 |
| SSTL-12 | V _{CCPT} | 1.2 | 1.8 | 0.6 | 0.6 |
| POD12 | V _{CCPT} | 1.2 | 1.8 | 0.84 | 1.2 |
| 1.8 V HSTL Class I and Class II | V _{CCPT} | 1.8 | 1.8 | 0.9 | 0.9 |
| 1.5 V HSTL Class I and Class II | V _{CCPT} | 1.5 | 1.8 | 0.75 | 0.75 |
| 1.2 V HSTL Class I and Class II | V _{CCPT} | 1.2 | 1.8 | 0.6 | 0.6 |
| HSUL-12 | V _{CCPT} | 1.2 | 1.8 | 0.6 | — |
| Differential SSTL-18 Class I and Class II | V _{CCPT} | 1.8 | 1.8 | — | 0.9 |
| Differential SSTL-15 Class I and Class II | V _{CCPT} | 1.5 | 1.8 | — | 0.75 |
| Differential SSTL-15 | V _{CCPT} | 1.5 | 1.8 | — | 0.75 |
| Differential SSTL-135 | V _{CCPT} | 1.35 | 1.8 | — | 0.675 |
| Differential SSTL-125 | V _{CCPT} | 1.25 | 1.8 | — | 0.625 |
| Differential SSTL-12 | V _{CCPT} | 1.2 | 1.8 | — | 0.6 |
| Differential POD12 | V _{CCPT} | 1.2 | 1.8 | — | 1.2 |
| Differential 1.8 V HSTL Class I and Class II | V _{CCPT} | 1.8 | 1.8 | — | 0.9 |
| Differential 1.5 V HSTL Class I and Class II | V _{CCPT} | 1.5 | 1.8 | — | 0.75 |
| Differential 1.2 V HSTL Class I and Class II | V _{CCPT} | 1.2 | 1.8 | — | 0.6 |
| Differential HSUL-12 | V _{CCPT} | 1.2 | 1.8 | — | — |

continued...

⁽⁵⁾ Input for the SSTL, HSTL, Differential SSTL, Differential HSTL, POD, Differential POD, LVDS, RSDS, Mini-LVDS, LVPECL, HSUL, and Differential HSUL are powered by V_{CCPT}



| I/O Standard | V _{CCIO} (V) | | V _{CCPT} (V) (Pre-Driver Voltage) | V _{REF} (V) (Input Ref Voltage) | V _{TT} (V) (Board Termination Voltage) |
|--|-----------------------|--------|---|---|--|
| | Input ⁽⁵⁾ | Output | | | |
| LVDS | V _{CCPT} | 1.8 | 1.8 | — | — |
| Mini-LVDS | V _{CCPT} | 1.8 | 1.8 | — | — |
| RSDS | V _{CCPT} | 1.8 | 1.8 | — | — |
| LVPECL (Differential clock input only) | V _{CCPT} | — | 1.8 | — | — |

Related Information

[I/O Standard Specifications, Intel Stratix 10 Device Datasheet](#)

2.2. I/O Element Structure in Intel Stratix 10 Devices

The I/O elements (IOEs) in Intel Stratix 10 devices contain a bidirectional I/O buffer and I/O registers to support a complete embedded bidirectional single data rate (SDR) or double data rate (DDR) transfer.

The IOEs are located in I/O columns within the core fabric of the Intel Stratix 10 device.

The Intel Stratix 10 SX devices also have IOEs for the HPS.

The GPIO IOE register consists of the DDR register, the half rate register, and the transmitter delay chains for input, output, and output enable (OE) paths:

- You can take data from the combinatorial path or the registered path.
- Only the core clock clocks the data.
- The half rate clock routed from the core clocks the half rate register.
- The full rate clock from the core clocks the full rate register.

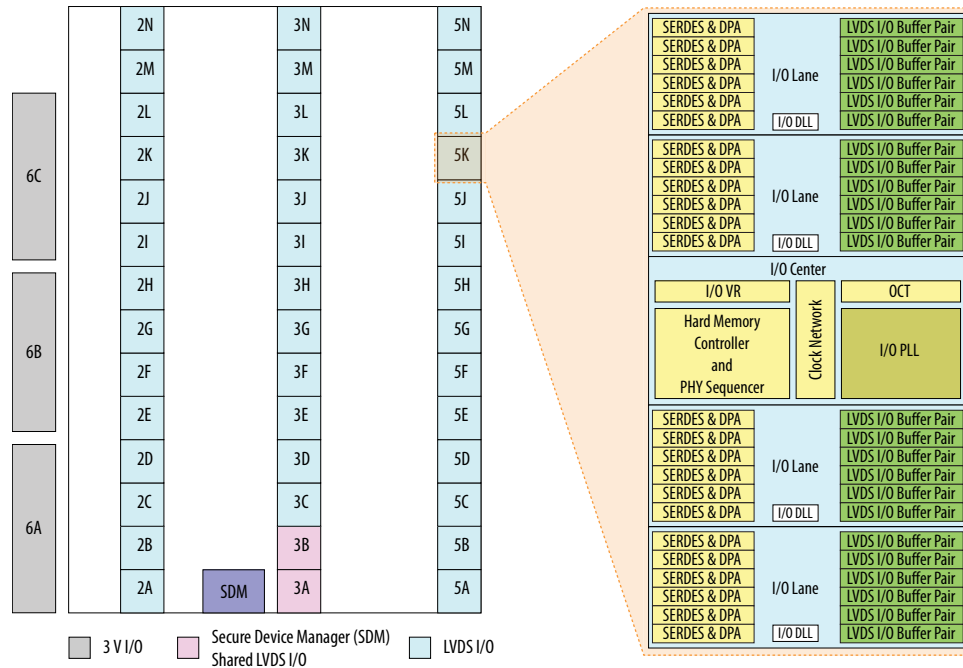
2.2.1. I/O Bank Architecture in Intel Stratix 10 Devices

In each LVDS I/O bank, there are four I/O lanes with 12 I/O pins in each lane. Other than the I/O lanes, each I/O bank also contains dedicated circuitries including the I/O PLL, DPA block, SERDES, hard memory controller, and I/O sequencer.

In each 3 V I/O bank, there are eight single-ended 3 V I/O buffers.

⁽⁵⁾ Input for the SSTL, HSTL, Differential SSTL, Differential HSTL, POD, Differential POD, LVDS, RS DS, Mini-LVDS, LVPECL, HSUL, and Differential HSUL are powered by V_{CCPT}

Figure 2. I/O Bank Structure



Related Information

- [Secure Device Manager, Intel Stratix 10 Configuration User Guide](#)
Provides more information about the Secure Device Manager.
- [Restrictions on I/O Bank Usage for Intel Stratix 10 EMIF with HPS, Intel Stratix 10 External Memory Interfaces User Guide](#)
Provides more information about the shared LVDS I/O banks that are used by the HPS SDRAM interface.

2.2.2. I/O Buffer and Registers in Intel Stratix 10 Devices

I/O registers are composed of the input path for handling data from the pin to the core, the output path for handling data from the core to the pin, and the output enable (OE) path for handling the OE signal to the output buffer. These registers allow faster source-synchronous register-to-register transfers and resynchronization. Use the GPIO Intel FPGA IP to utilize these registers to implement DDR circuitry.

The input and output paths contains the following blocks:

- Input registers—support half/full rate data transfer from peripheral to core, and support double or single data rate data capture from I/O buffer.
- Output registers—support half/full rate data transfer from core to peripheral, and support double or single data rate data transfer to I/O buffer.
- OE registers—support half or full rate data transfer from core to peripheral, and support single data rate data transfer to I/O buffer.

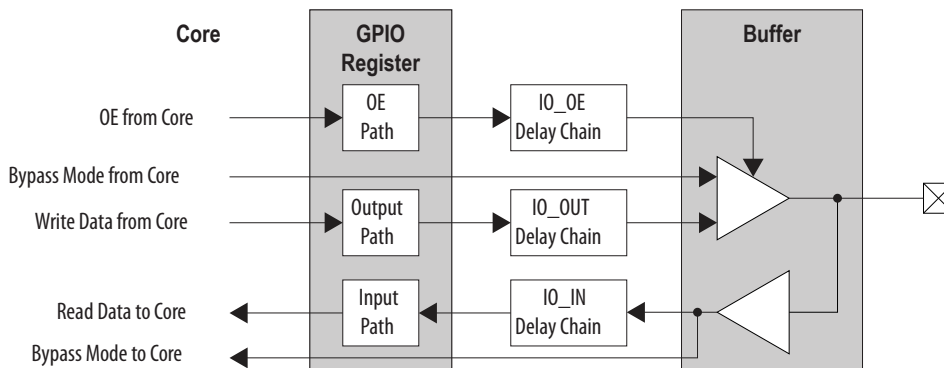


The input and output paths also support the following features:

- Clock enable.
- Asynchronous or synchronous reset.
- Bypass mode for input and output paths.
- Delays chains on input and output paths.

Figure 3. IOE Structure for Intel Stratix 10 Devices

This figure shows the Intel Stratix 10 FPGA IOE structure.



Note: The GPIOs in the 3 V I/O banks do not have I/O registers.

2.3. Programmable IOE Features in Intel Stratix 10 Devices

Table 4. Intel Stratix 10 Programmable IOE Features Settings and Assignment Name

| Feature | Setting | Condition | Intel Quartus Prime Assignment Name |
|-----------------------------|---|--|---|
| Slew Rate Control | 0 (Slow), 1 (Fast). Default is 1. | Disabled if you use the R _S OCT feature. | SLEW_RATE |
| I/O Delay | Refer to the device datasheet | — | INPUT_DELAY_CHAIN OUTPUT_DELAY_CHAIN |
| Open-Drain Output | On, Off. Default is Off | — | AUTO_OPEN_DRAIN_PINS |
| Bus-Hold | On, Off. Default is Off. | Disabled if you use the weak pull-up resistor feature. | ENABLE_BUS_HOLD_CIRCUITRY |
| Weak Pull-up Resistor | On, Off. Default is Off. | Disabled if you use the bus-hold feature. | WEAK_PULL_UP_RESISTOR |
| Pre-Emphasis | 0 (disabled), 1 (enabled). Default is 1. | — | PROGRAMMABLE_PREEMPHASIS |
| Differential Output Voltage | 0 (low), 1 (medium low), 2 (medium high), 3 (high). Default is 2. | — | PROGRAMMABLE_VOD |



Table 5. Intel Stratix 10 Programmable IOE Features I/O Buffer Types and I/O Standards Support

This table lists the I/O buffer types and I/O standards that support the programmable IOE features. For information about which I/O standards are available for each I/O buffer type, refer to the related information.

| Feature | I/O Buffer Type Support | | | I/O Standards Support |
|-----------------------------|-------------------------|---------|----------------------------|--|
| | LVDS I/O | 3 V I/O | HPS I/O (SoC Devices Only) | |
| Slew Rate Control | Yes | Yes | Yes | <ul style="list-style-type: none"> • 3.0 V LVTTTL • 1.2 V, 1.5 V, 1.8 V, 2.5 V, and 3.0 V LVCMOS • SSTL-18, SSTL-15, SSTL-135, SSTL-125, and SSTL-12 • 1.2 V, 1.5 V, and 1.8 V HSTL • HSUL-12 • POD12 • Differential SSTL-18, Differential SSTL-15, Differential SSTL-135, Differential SSTL-125, and Differential SSTL-12 • Differential 1.2 V, 1.5 V, and 1.8 V HSTL • Differential HSUL-12 |
| I/O Delay | Yes | Yes | — | |
| Open-Drain Output | Yes | Yes | Yes | |
| Bus-Hold | Yes | Yes | — | |
| Weak Pull-up Resistor | Yes | Yes | Yes | <ul style="list-style-type: none"> • 3.0 V LVTTTL • 1.2 V, 1.5 V, 1.8 V, and 3.0 V LVCMOS |
| Pre-Emphasis | Yes | — | — | |
| Differential Output Voltage | Yes | — | — | <ul style="list-style-type: none"> • LVDS • RSDS • Mini-LVDS • LVPECL • With OCT fast slew rate mode: <ul style="list-style-type: none"> — POD12 and Differential POD12 — SSTL-12 and Differential SSTL-12 |

Related Information

- [Intel Stratix 10 Device Datasheet](#)
- [Intel Stratix 10 I/O Standards Support](#) on page 8
Lists the I/O standards supported by the LVDS I/O, 3 V I/O, and HPS I/O buffers.

2.3.1. Programmable Output Slew Rate Control

You can specify the slew rate on a pin-by-pin basis because each I/O pin contains a slew rate control. The slew rate control affects both the rising and falling edges.



You can select between two slew rate settings, 1 and 0:

- Fast slew rate (1)—provides high-speed transitions for high-performance systems. This is the default setting. If you enable on-chip termination (OCT), this setting is always used.
- Slow slew rate (0)—reduces system noise and crosstalk but adds a nominal delay to the rising and falling edges.

Note: Intel recommends that you perform IBIS or SPICE simulations to determine the best slew rate setting for your specific application.

2.3.2. Programmable IOE Delay

You can activate the programmable IOE delays to ensure zero hold time, minimize setup time, or increase clock-to-output time. This feature helps read and write timing margins because it minimizes the uncertainties between signals in the bus.

Each pin can have a different input delay from pin-to-input register or a delay from output register-to-output pin values to ensure that the signals within a bus have the same delay going into or out of the device.

For more information about the programmable IOE delay specifications, refer to the device datasheet.

Related Information

[Programmable IOE Delay, Intel Stratix 10 Device Datasheet](#)

2.3.3. Programmable Open-Drain Output

The programmable open-drain output provides a high-impedance state on output when logic to the output buffer is high. If logic to the output buffer is low, output is low.

You can attach several open-drain output to a wire. This connection type is like a logical OR function and is commonly called an active-low wired-OR circuit. If at least one of the outputs is in logic 0 state (active), the circuit sinks the current and brings the line to low voltage.

You can use open-drain output if you are connecting multiple devices to a bus. For example, you can use the open-drain output for system-level control signals that can be asserted by any device or as an interrupt.

You can enable the open-drain output assignment using one of these methods:

- Design the tristate buffer using OPNDRN primitive.
- Turn on the **Auto Open-Drain Pins** option in the Intel Quartus Prime software.

You can design open-drain output without enabling the option assignment. However, your design will not use the I/O buffer's open-drain output feature. The open-drain output feature of the I/O buffer provides you the best propagation delay from OE to output.



Note: Do not pull the output voltage higher than the V_i (DC) level. Intel recommends that you perform HSPICE simulation to verify the output voltage in your selected topology. You must ensure the output voltage meets the V_{IH} and V_{IL} requirements of the receiving device.

Related Information

[Plan Stage Reports, Compiler User Guide, Intel Quartus Prime Pro Edition](#)

Provides more information about the Fitter Plan Stage report that you can use to check the I/O pins settings.

2.3.4. Programmable Bus Hold

Each I/O pin provides an optional bus-hold feature that is active only after configuration. When the device enters user mode, the bus-hold circuit captures the value that is present on the pin by the end of the configuration.

The bus-hold circuitry uses a resistor with a nominal resistance (R_{BH}), approximately 7 k Ω , to weakly pull the signal level to the last-driven state of the pin. The bus-hold circuitry holds this pin state until the next input signal is present. Because of this, you do not require an external pull-up or pull-down resistor to hold a signal level when the bus is tri-stated.

For each I/O pin, you can individually specify that the bus-hold circuitry pulls non-driven pins away from the input threshold voltage—where noise can cause unintended high-frequency switching. To prevent over-driving signals, the bus-hold circuitry drives the voltage level of the I/O pin lower than the V_{CCIO} level.

If you enable the bus-hold feature, you cannot use the programmable pull-up option. To configure the I/O pin for differential signals, disable the bus-hold feature.

2.3.5. Programmable Pull-Up Resistor

Each I/O pin provides an optional programmable pull-up resistor during user mode. The pull-up resistor weakly holds the I/O to the V_{CCIO} level.

The Intel Stratix 10 device supports programmable weak pull-up resistors only on user I/O pins but not on dedicated configuration pins, dedicated clock pins, or JTAG pins .

If you enable the weak pull-up resistor, you cannot use the bus-hold feature.

2.3.6. Programmable Pre-Emphasis

The V_{OD} setting and the output impedance of the driver set the output current limit of a high-speed transmission signal. At a high frequency, the slew rate may not be fast enough to reach the full V_{OD} level before the next edge, producing pattern-dependent jitter. With pre-emphasis, the output current is boosted momentarily during switching to increase the output slew rate.

Pre-emphasis increases the amplitude of the high-frequency component of the output signal, and thus helps to compensate for the frequency-dependent attenuation along the transmission line. The overshoot introduced by the extra current happens only during a change of state switching to increase the output slew rate and does not ring,



unlike the overshoot caused by signal reflection. The amount of pre-emphasis required depends on the attenuation of the high-frequency component along the transmission line.

Figure 4. Programmable Pre-Emphasis

This figure shows the LVDS output with pre-emphasis.

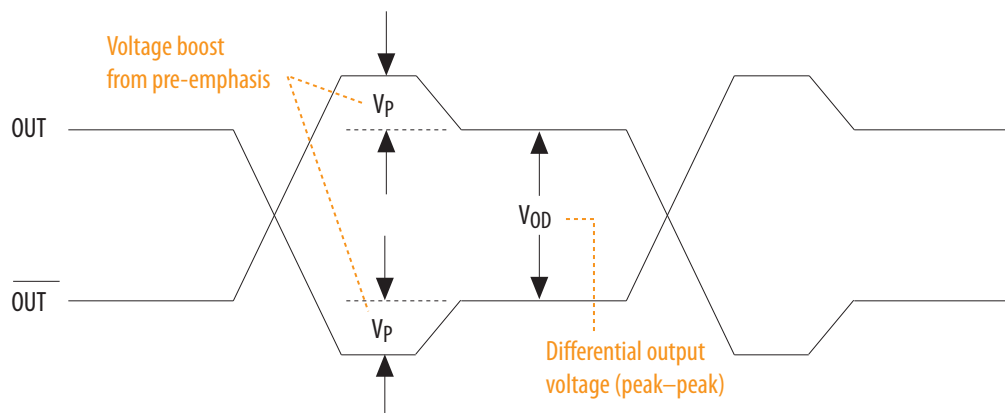


Table 6. Intel Quartus Prime Software Assignment Editor—Programmable Pre-Emphasis

This table lists the assignment name for programmable pre-emphasis and its possible values in the Intel Quartus Prime software Assignment Editor.

| Field | Assignment |
|-----------------|--|
| To | tx_out |
| Assignment name | Programmable Pre-emphasis |
| Allowed values | 0 (disabled), 1 (enabled). Default is 1. |

2.3.7. Programmable Differential Output Voltage

The programmable V_{OD} settings allow you to adjust the output eye opening to optimize the trace length and power consumption. A higher V_{OD} swing improves voltage margins at the receiver end, and a smaller V_{OD} swing reduces power consumption. You can statically adjust the V_{OD} of the differential signal by changing the V_{OD} settings in the Intel Quartus Prime software Assignment Editor.

Figure 5. Differential V_{OD}

This figure shows the V_{OD} of the differential LVDS output.

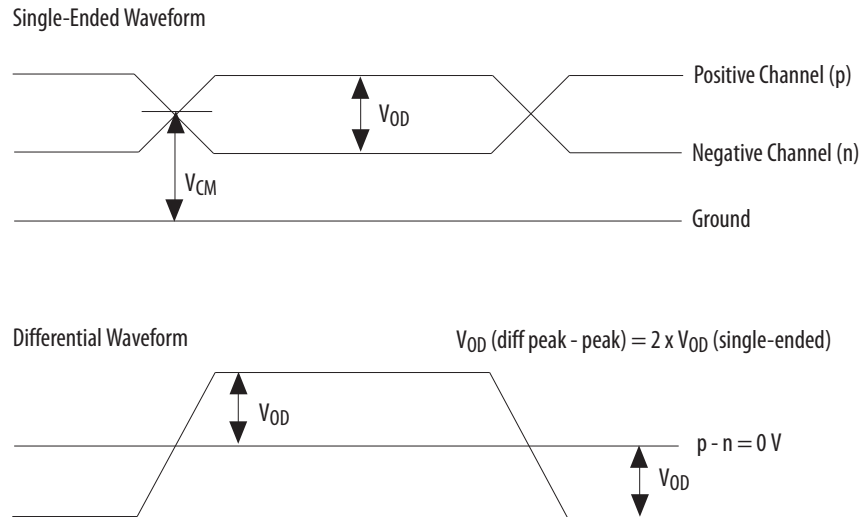


Table 7. Intel Quartus Prime Software Assignment Editor—Programmable V_{OD}

This table lists the assignment name for programmable V_{OD} and its possible values in the Intel Quartus Prime software Assignment Editor.

| Field | Assignment |
|-----------------|---|
| To | tx_out |
| Assignment name | Programmable Differential Output Voltage (V_{OD}) |
| Allowed values | 0 (low), 1 (medium low), 2 (medium high), 3 (high). Default is 2. |

2.3.8. Programmable Current Strength

You can use the programmable current strength to mitigate the effects of high signal attenuation that is caused by a long transmission line or a legacy backplane.

Note:

To use programmable current strength, you must specify the current strength assignment in the Intel Quartus Prime software. Without explicit assignments, the Intel Quartus Prime software uses these predefined default values:

- All HSTL and SSTL Class I, and all non-voltage-referenced I/O standards—50 Ω R_S OCT without calibration
- All HSTL and SSTL Class II I/O standards—25 Ω R_S OCT without calibration
- POD12 I/O standard—34 Ω R_S OCT without calibration

**Table 8. Programmable Current Strength Settings for Intel Stratix 10 Devices**

The output buffer for each Intel Stratix 10 device I/O pin has a programmable current strength control for the I/O standards listed in this table.

| I/O Standard | I _{OH} / I _{OL} Current Strength Setting (mA) | | | |
|-------------------------------|---|---------|---|---------|
| | Supported in FPGA | | Supported in HPS ⁽⁶⁾ (SoC Devices Only) | |
| | Available | Default | Available | Default |
| 3.0 V LVTTTL ⁽⁷⁾ | 24, 20, 16, 12, 8, 4 | 12 | — | — |
| 3.0 V LVCMOS ⁽⁷⁾ | 16, 12, 8, 4 | 12 | — | — |
| 2.5 V LVCMOS | 16, 12, 8, 4 | 12 | — | — |
| 1.8 V LVCMOS | 16, 12, 10, 8, 6, 4, 2 | 12 | 12, 10, 8 | 12 |
| 1.5 V LVCMOS | 12, 10, 8, 6, 4, 2 | 12 | — | — |
| 1.2 V LVCMOS | 8, 6, 4, 2 | 8 | — | — |
| SSTL-18 Class I | 8, 6, 4 | 8 | — | — |
| SSTL-18 Class II | 8 | 8 | — | — |
| SSTL-15 Class I | 8, 6, 4 | 8 | — | — |
| SSTL-15 Class II | 8 | 8 | — | — |
| SSTL-135 | 8, 6, 4 | 8 | — | — |
| SSTL-125 | 8, 6, 4 | 8 | — | — |
| SSTL-12 | 8, 6, 4 | 8 | — | — |
| POD12 | 8, 6, 4 | 8 | — | — |
| 1.8 V HSTL Class I | 12, 10, 8, 6, 4 | 8 | — | — |
| 1.8 V HSTL Class II | 14 | 14 | — | — |
| 1.5 V HSTL Class I | 12, 10, 8, 6, 4 | 8 | — | — |
| 1.5 V HSTL Class II | 14 | 14 | — | — |
| 1.2 V HSTL Class I | 8, 6, 4 | 8 | — | — |
| Differential SSTL-18 Class I | 8, 6, 4 | 8 | — | — |
| Differential SSTL-18 Class II | 8 | 8 | — | — |
| Differential SSTL-15 Class I | 8, 6, 4 | 8 | — | — |
| Differential SSTL-15 Class II | 8 | 8 | — | — |
| Differential SSTL-135 | 12, 10, 8, 6, 4 | 8 | — | — |
| Differential SSTL-125 | 12, 10, 8, 6, 4 | 8 | — | — |
| Differential SSTL-12 Class I | 12, 10, 8, 6, 4 | 8 | — | — |
| Differential POD12 | 8, 6, 4 | 8 | — | — |

continued...

⁽⁶⁾ The programmable current strength information for the HPS is preliminary.

⁽⁷⁾ Programmable slew rate control is applicable only for current strength settings of 16 mA and above.

| I/O Standard | I _{OH} / I _{OL} Current Strength Setting (mA) | | | |
|----------------------------------|---|---------|---|---------|
| | Supported in FPGA | | Supported in HPS ⁽⁶⁾ (SoC Devices Only) | |
| | Available | Default | Available | Default |
| Differential 1.8 V HSTL Class I | 12, 10, 8, 6, 4 | 8 | — | — |
| Differential 1.8 V HSTL Class II | 14 | 14 | — | — |
| Differential 1.5 V HSTL Class I | 12, 10, 8, 6, 4 | 8 | — | — |
| Differential 1.5 V HSTL Class II | 14 | 14 | — | — |
| Differential 1.2 V HSTL Class I | 8, 6, 4 | 8 | — | — |

Note: Intel recommends that you perform IBIS or SPICE simulations to determine the best current strength setting for your specific application.

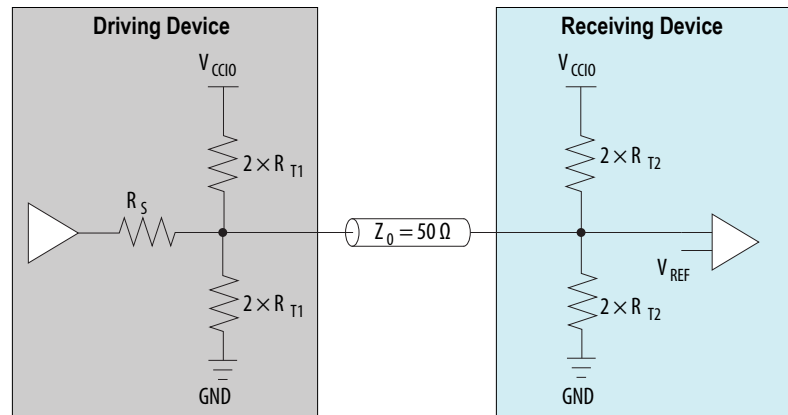
2.4. On-Chip I/O Termination in Intel Stratix 10 Devices

Serial (R_S) and parallel (R_T) OCT provides I/O impedance matching and termination capabilities. OCT maintains signal quality, saves board space, and reduces external component costs.

The Intel Stratix 10 devices support OCT in all FPGA I/O banks. For the 3 V I/Os, the I/Os support only OCT without calibration.

Figure 6. Single-ended Termination (R_S and R_T)

This figure shows the single-ended termination schemes supported in Intel Stratix 10 devices. R_{T1} and R_{T2} are dynamic parallel terminations and are enabled only if the device is receiving. In bidirectional applications, R_{T1} and R_{T2} are automatically switched on when the device is receiving and switched off when the device is driving.



⁽⁶⁾ The programmable current strength information for the HPS is preliminary.



Table 9. OCT Schemes Supported in Intel Stratix 10 Devices

| Direction | OCT Schemes | I/O Type Support | |
|---------------|---|------------------|---------|
| | | LVDS I/O | 3 V I/O |
| Output | R _S OCT with calibration | Yes | — |
| | R _S OCT without calibration | Yes | — |
| Input | R _T OCT with calibration | Yes | — |
| | R _D OCT (LVDS I/O standard only) | Yes | — |
| Bidirectional | Dynamic R _S and R _T OCT | Yes | — |

2.4.1. R_S OCT without Calibration in Intel Stratix 10 Devices

The Intel Stratix 10 devices support R_S OCT for single-ended and voltage-referenced I/O standards. R_S OCT without calibration is supported on output only.

Table 10. Selectable I/O Standards for R_S OCT Without Calibration

This table lists the output termination settings for uncalibrated OCT on different I/O standards.

| I/O Standard | Uncalibrated OCT (Output) |
|---------------------------|---------------------------|
| | R _S (Ω) |
| 3.0 V LVTTTL/3.0 V LVCMOS | 25, 50 |
| 2.5 V LVCMOS | 25, 50 |
| 1.8 V LVCMOS | 25, 50 |
| 1.5 V LVCMOS | 25, 50 |
| 1.2 V LVCMOS | 25, 50 |
| SSTL-18 Class I | 50 |
| SSTL-18 Class II | 25 |
| SSTL-15 Class I | 50 |
| SSTL-15 Class II | 25 |
| SSTL-15 | 34, 40 |
| SSTL-135 | 34, 40 |
| SSTL-125 | 34, 40 |
| SSTL-12 | 34, 40, 60, 120, 240 |
| POD12 | 34, 40, 48, 60 |
| 1.8 V HSTL Class I | 50 |
| 1.8 V HSTL Class II | 25 |
| 1.5 V HSTL Class I | 50 |
| 1.5 V HSTL Class II | 25 |
| 1.2 V HSTL Class I | 50 |
| 1.2 V HSTL Class II | 25 |
| HSUL-12 | 34, 40, 48, 60, 80 |

continued...

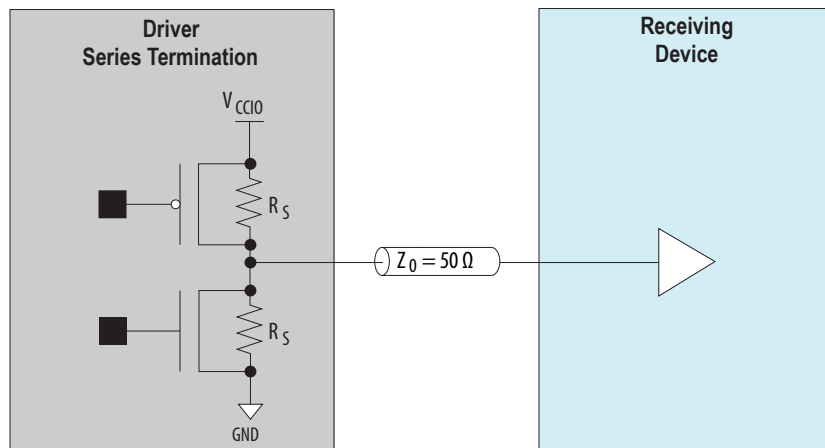
| I/O Standard | Uncalibrated OCT (Output) |
|----------------------------------|---------------------------|
| | R_s (Ω) |
| Differential SSTL-18 Class I | 50 |
| Differential SSTL-18 Class II | 25 |
| Differential SSTL-15 Class I | 50 |
| Differential SSTL-15 Class II | 25 |
| Differential SSTL-15 | 34, 40 |
| Differential SSTL-15 Class I | 50 |
| Differential SSTL-15 Class II | 25 |
| Differential SSTL-135 | 34, 40 |
| Differential SSTL-125 | 34, 40 |
| Differential SSTL-12 | 34, 40, 60, 120, 240 |
| Differential POD12 | 34, 40, 48, 60 |
| Differential 1.8 V HSTL Class I | 50 |
| Differential 1.8 V HSTL Class II | 25 |
| Differential 1.5 V HSTL Class I | 50 |
| Differential 1.5 V HSTL Class II | 25 |
| Differential 1.2 V HSTL Class I | 50 |
| Differential 1.2 V HSTL Class II | 25 |
| Differential HSUL-12 | 34, 40, 48, 60, 80 |

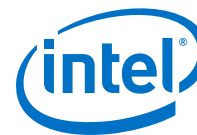
Driver-impedance matching provides the I/O driver with controlled output impedance that closely matches the impedance of the transmission line. As a result, you can significantly reduce signal reflections on PCB traces.

If you use impedance matching, you cannot specify the current strength.

Figure 7. R_s OCT Without Calibration

This figure shows the R_s as the intrinsic impedance of the output transistors.





2.4.2. R_SOCT with Calibration in Intel Stratix 10 Devices

The Intel Stratix 10 devices support R_S OCT with calibration in all LVDS I/O banks.

Table 11. Selectable I/O Standards for R_S OCT With Calibration

This table lists the output termination settings for calibrated OCT on different I/O standards.

| I/O Standard | Calibrated OCT (Output) | |
|-------------------------------|-------------------------|---------|
| | R _S (Ω) | RZQ (Ω) |
| 1.8 V LVCMOS | 25, 50 | 100 |
| 1.5 V LVCMOS | 25, 50 | 100 |
| 1.2 V LVCMOS | 25, 50 | 100 |
| SSTL-18 Class I | 50 | 100 |
| SSTL-18 Class II | 25 | 100 |
| SSTL-15 Class I | 50 | 100 |
| SSTL-15 Class II | 25 | 100 |
| SSTL-15 | 34, 40 | 240 |
| SSTL-135 | 34, 40 | 240 |
| SSTL-125 | 34, 40 | 240 |
| SSTL-12 | 34, 40, 60, 120, 240 | 240 |
| POD12 | 34, 40, 48, 60 | 240 |
| 1.8 V HSTL Class I | 50 | 100 |
| 1.8 V HSTL Class II | 25 | 100 |
| 1.5 V HSTL Class I | 50 | 100 |
| 1.5 V HSTL Class II | 25 | 100 |
| 1.2 V HSTL Class I | 50 | 100 |
| 1.2 V HSTL Class II | 25 | 100 |
| HSUL-12 | 34, 40, 48, 60, 80 | 240 |
| Differential SSTL-18 Class I | 50 | 100 |
| Differential SSTL-18 Class II | 25 | 100 |
| Differential SSTL-15 Class I | 50 | 100 |
| Differential SSTL-15 Class II | 25 | 100 |
| Differential SSTL-15 | 34, 40 | 240 |
| Differential SSTL-135 | 34, 40 | 240 |
| Differential SSTL-15 Class I | 50 | 100 |
| Differential SSTL-15 Class II | 25 | 100 |
| Differential SSTL-125 | 34, 40 | 240 |
| Differential SSTL-12 | 34, 40, 60, 120, 240 | 240 |
| Differential POD12 | 34, 40, 48, 60 | 240 |

continued...

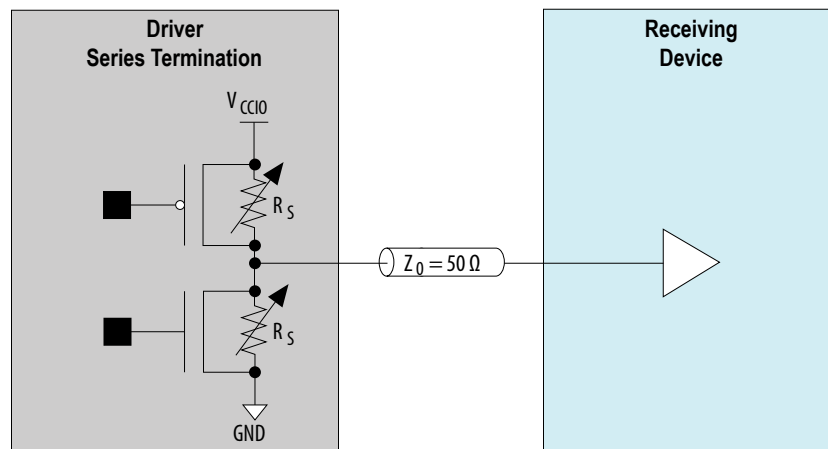
| I/O Standard | Calibrated OCT (Output) | |
|----------------------------------|-------------------------|-----------------------|
| | R_S (Ω) | R_{ZQ} (Ω) |
| Differential 1.8 V HSTL Class I | 50 | 100 |
| Differential 1.8 V HSTL Class II | 25 | 100 |
| Differential 1.5 V HSTL Class I | 50 | 100 |
| Differential 1.5 V HSTL Class II | 25 | 100 |
| Differential 1.2 V HSTL Class I | 50 | 100 |
| Differential 1.2 V HSTL Class II | 25 | 100 |
| Differential HSUL-12 | 34, 40, 48, 60, 80 | 240 |

The R_S OCT calibration circuit compares the total impedance of the I/O buffer to the external reference resistor connected to the R_{ZQ} pin and dynamically enables or disables the transistors until they match.

Calibration occurs at the end of device configuration. When the calibration circuit finds the correct impedance, the circuit powers down and stops changing the characteristics of the drivers.

Figure 8. R_S OCT with Calibration

This figure shows the R_S as the intrinsic impedance of the output transistors.



2.4.3. R_T OCT with Calibration in Intel Stratix 10 Devices

The Intel Stratix 10 devices support R_T OCT with calibration in all LVDS I/O banks but not in the 3 V I/O banks. R_T OCT with calibration is available only for configuration of input and bidirectional pins. Output pin configurations do not support R_T OCT with calibration. If you use R_T OCT, the V_{CCIO} of the bank must match the I/O standard of the pin where you enable the R_T OCT.

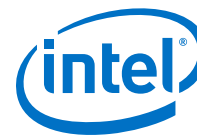


Table 12. Selectable I/O Standards for R_TOCT With Calibration

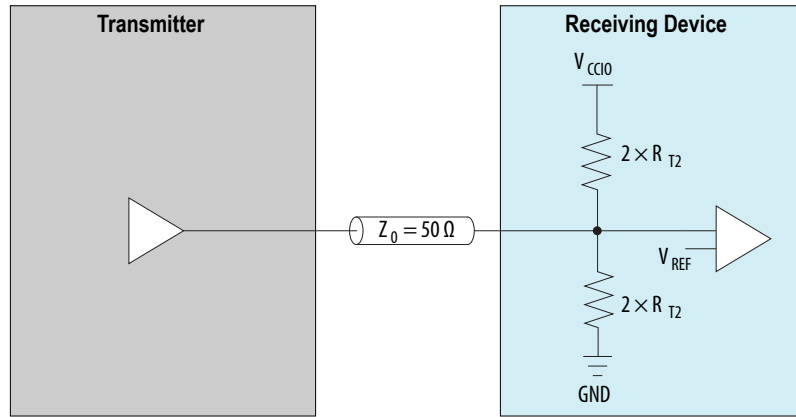
This table lists the input termination settings for calibrated OCT on different I/O standards.

| I/O Standard | Calibrated OCT (Input) | |
|----------------------------------|------------------------------|---------|
| | R _T (Ω) | RZQ (Ω) |
| SSTL-18 Class I | 50 | 100 |
| SSTL-18 Class II | 50 | 100 |
| SSTL-15 Class I | 50 | 100 |
| SSTL-15 Class II | 50 | 100 |
| SSTL-15 | 48, 60, 120 | 240 |
| SSTL-135 | 48, 60, 120 | 240 |
| SSTL-125 | 48, 60, 120 | 240 |
| SSTL-12 | 60, 120 | 240 |
| POD12 | 34, 40, 48, 60, 80, 120, 240 | 240 |
| 1.8 V HSTL Class I | 50 | 100 |
| 1.8 V HSTL Class II | 50 | 100 |
| 1.5 V HSTL Class I | 50 | 100 |
| 1.5 V HSTL Class II | 50 | 100 |
| 1.2 V HSTL Class I | 50 | 100 |
| 1.2 V HSTL Class II | 50 | 100 |
| Differential SSTL-18 Class I | 50 | 100 |
| Differential SSTL-18 Class II | 50 | 100 |
| Differential SSTL-15 Class I | 50 | 100 |
| Differential SSTL-15 Class II | 50 | 100 |
| Differential SSTL-15 | 48, 60, 120 | 240 |
| Differential SSTL-135 | 48, 60, 120 | 240 |
| Differential SSTL-125 | 48, 60, 120 | 240 |
| Differential SSTL-12 | 60, 120 | 240 |
| Differential POD12 | 34, 40, 48, 60, 80, 120, 240 | 240 |
| Differential 1.8 V HSTL Class I | 50 | 100 |
| Differential 1.8 V HSTL Class II | 50 | 100 |
| Differential 1.5 V HSTL Class I | 50 | 100 |
| Differential 1.5 V HSTL Class II | 50 | 100 |
| Differential 1.2 V HSTL Class I | 50 | 100 |
| Differential 1.2 V HSTL Class II | 50 | 100 |

The R_T OCT calibration circuit compares the total impedance of the I/O buffer to the external resistor connected to the RZQ pin. The circuit dynamically enables or disables the transistors until the total impedance of the I/O buffer matches the external resistor.

Calibration occurs at the end of the device configuration. When the calibration circuit finds the correct impedance, the circuit powers down and stops changing the characteristics of the drivers.

Figure 9. R_T OCT with Calibration



2.4.4. Dynamic OCT

Dynamic OCT is useful for terminating a high-performance bidirectional path by optimizing the signal integrity depending on the direction of the data. Dynamic OCT also helps save power because device termination is internal—termination switches on only during input operation and thus draw less static power.

Note: If you use the SSTL-15, SSTL-135, and SSTL-125 I/O standards with the DDR3 memory interface, Intel recommends that you use OCT with these I/O standards to save board space and cost. OCT reduces the number of external termination resistors used.

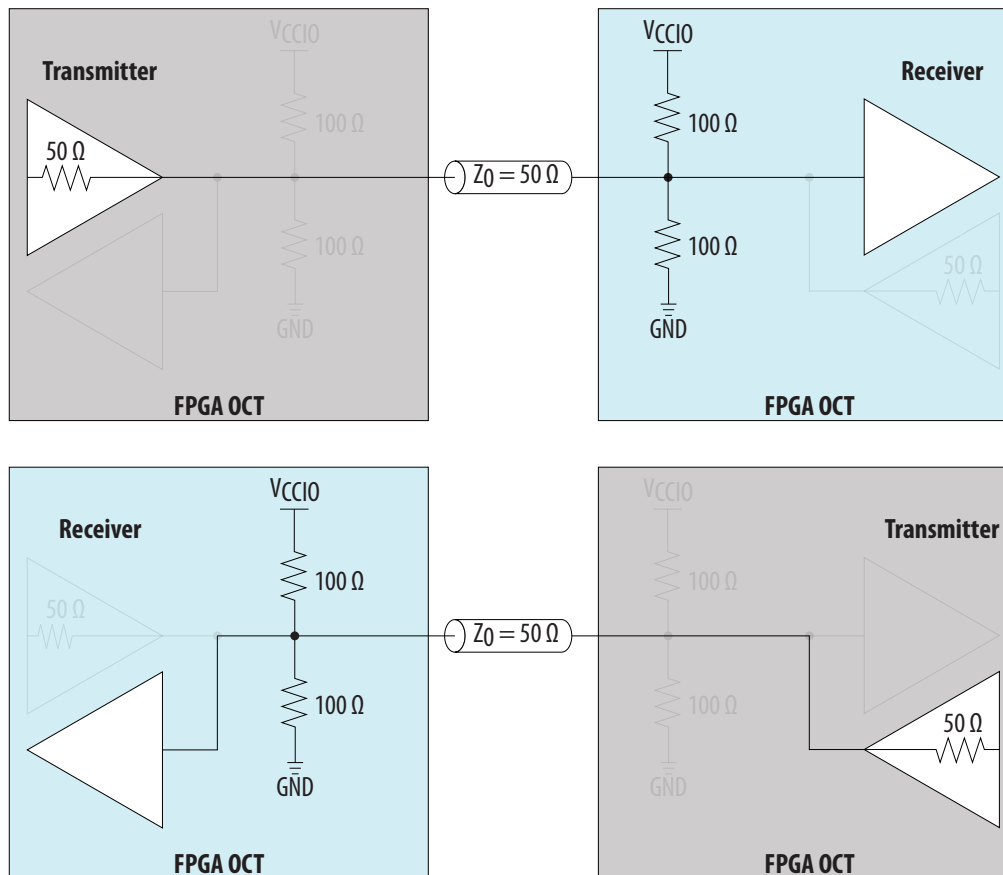
Table 13. Dynamic OCT Based on Bidirectional I/O

Dynamic R_T OCT or R_S OCT is enabled or disabled based on whether the bidirectional I/O acts as a receiver or driver.

| Dynamic OCT | Bidirectional I/O | State |
|----------------------------|--------------------|----------|
| Dynamic R _T OCT | Acts as a receiver | Enabled |
| | Acts as a driver | Disabled |
| Dynamic R _S OCT | Acts as a receiver | Disabled |
| | Acts as a driver | Enabled |



Figure 10. Dynamic R_T OCT in Intel Stratix 10 Devices



Related Information

[PHY Lite for Parallel Interfaces Intel FPGA IP Core User Guide: Intel Stratix 10, Intel Arria® 10, and Intel Cyclone® 10 GX Devices](#)

Provides more information for applications that require dynamic OCT for bidirectional pins.

2.4.5. Differential Input R_D OCT

All I/O pins and dedicated clock input pins in Intel Stratix 10 devices support on-chip differential termination, R_D OCT. The Intel Stratix 10 devices provide a 100 Ω , on-chip differential termination option on each differential receiver channel for LVDS standards.

You can enable on-chip termination in the Intel Quartus Prime software Assignment Editor.

Figure 11. On-Chip Differential I/O Termination

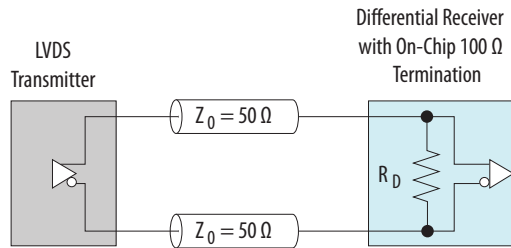


Table 14. Intel Quartus Prime Software Assignment Editor—On-Chip Differential Termination

This table lists the assignment name for on-chip differential termination in the Intel Quartus Prime software Assignment Editor.

| Field | Assignment |
|-----------------|-------------------|
| To | rx_in |
| Assignment name | Input Termination |
| Value | Differential |

2.4.6. OCT Calibration Block in Intel Stratix 10 Devices

You can calibrate the OCT using the OCT calibration block available in each I/O bank.

You can use R_S and R_T OCT in the same I/O bank for different I/O standards if the I/O standards use the same V_{CCIO} supply voltage. You cannot configure the R_S OCT and the programmable current strength for the same I/O buffer.

The OCT calibration process uses the RZQ pin that is available in every calibration block in a given I/O bank for series- and parallel-calibrated termination:

- Each OCT calibration block has an external 240 Ω reference resistor associated with it through the RZQ pin.
- Connect the RZQ pin to GND through an external 100 Ω or 240 Ω resistor (depending on the R_S or R_T OCT value).
- The RZQ pin shares the same V_{CCIO} supply voltage with the I/O bank where the pin is located.
- The RZQ pin is a dual-purpose I/O pin and functions as a general purpose I/O pin if you do not use the calibration circuit.

Intel Stratix 10 devices support calibrated R_S and calibrated R_T OCT on all LVDS I/O pins except for dedicated configuration pins.

2.5. External I/O Termination for Intel Stratix 10 Devices

Table 15. External Termination Schemes for Various I/O Standards

| I/O Standard | External Termination Scheme |
|---------------------------|----------------------------------|
| 3.0 V LVTTTL/3.0 V LVCMOS | No external termination required |
| 2.5 V LVCMOS | |

continued...



| I/O Standard | External Termination Scheme |
|--|--|
| 1.8 V LVCMOS | |
| 1.5 V LVCMOS | |
| 1.2 V LVCMOS | |
| SSTL-18 Class I and Class II | Single-Ended SSTL I/O Standard Termination |
| SSTL-15 Class I and Class II | |
| SSTL-15 ⁽⁸⁾ | No external termination required |
| SSTL-135 ⁽⁸⁾ | |
| SSTL-125 ⁽⁸⁾ | |
| SSTL-12 | |
| POD12 | Single-Ended POD I/O Standard Termination |
| 1.8 V HSTL Class I and Class II | Single-Ended HSTL I/O Standard Termination |
| 1.5 V HSTL Class I and Class II | |
| 1.2 V HSTL Class I and Class II | |
| HSUL-12 | No external termination required |
| Differential SSTL-18 Class I and Class II | Differential SSTL I/O Standard Termination |
| Differential SSTL-15 Class I and Class II | |
| Differential SSTL-15 ⁽⁸⁾ | No external termination required |
| Differential SSTL-135 ⁽⁸⁾ | |
| Differential SSTL-125 ⁽⁸⁾ | |
| Differential SSTL-12 | |
| Differential POD12 | Differential POD I/O Standard Termination |
| Differential 1.8 V HSTL Class I and Class II | Differential HSTL I/O Standard Termination |
| Differential 1.5 V HSTL Class I and Class II | |
| Differential 1.2 V HSTL Class I and Class II | |
| Differential HSUL-12 | No external termination required |
| LVDS | LVDS I/O Standard Termination |
| RSDS | RSDS/mini-LVDS I/O Standard Termination |
| Mini-LVDS | |
| LVPECL | Differential LVPECL I/O Standard Termination |

2.5.1. Single-Ended I/O Termination

Voltage-referenced I/O standards require an input V_{REF} and a termination voltage (V_{TT}). The reference voltage of the receiving device tracks the termination voltage of the transmitting device.

⁽⁸⁾ Intel recommends that you use OCT with these I/O standards to save board space and cost. OCT reduces the number of external termination resistors used.

The supported I/O standards such as SSTL-12, SSTL-125, SSTL-135, and SSTL-15 typically do not require external board termination.

Intel recommends that you use OCT with these I/O standards to save board space and cost. OCT reduces the number of external termination resistors used.

Note: You cannot use R_S and R_T OCT simultaneously. For more information, refer to the related information.

Figure 12. SSTL I/O Standard Termination

This figure shows the details of SSTL I/O termination on Intel Stratix 10 devices.

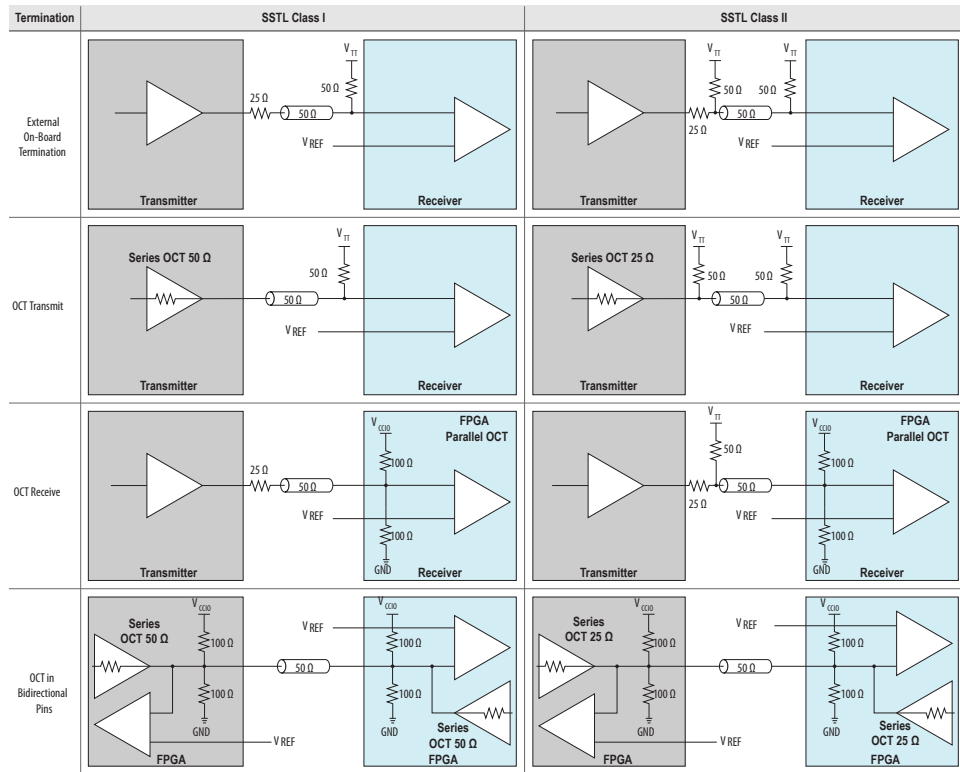




Figure 13. HSTL I/O Standard Termination

This figure shows the details of HSTL I/O termination on the Intel Stratix 10 devices.

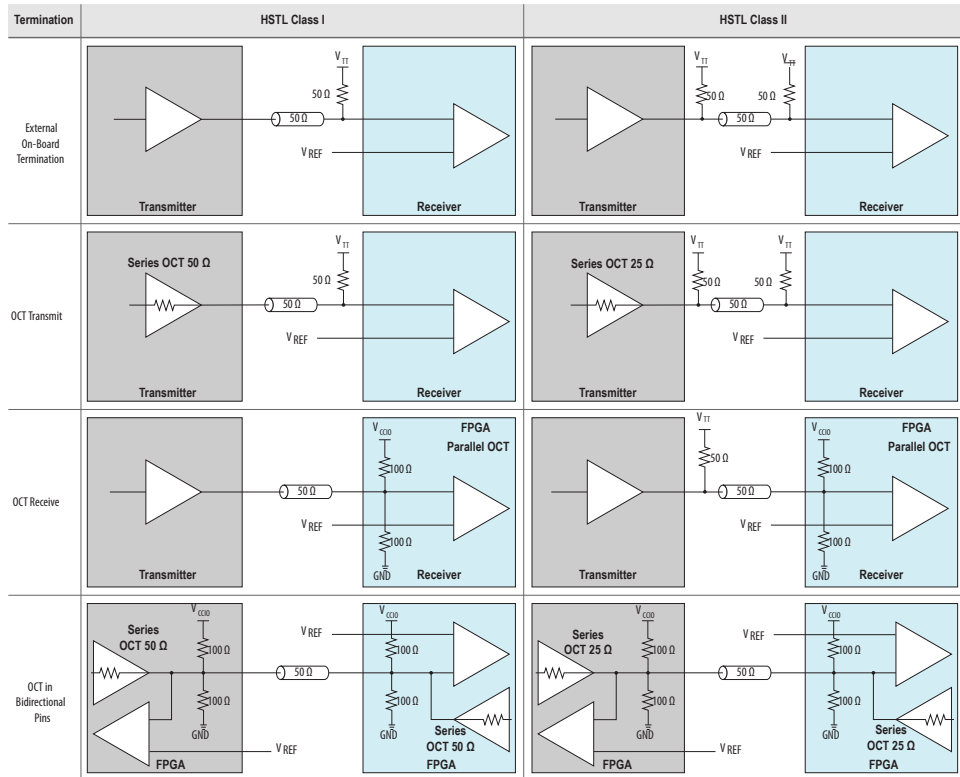
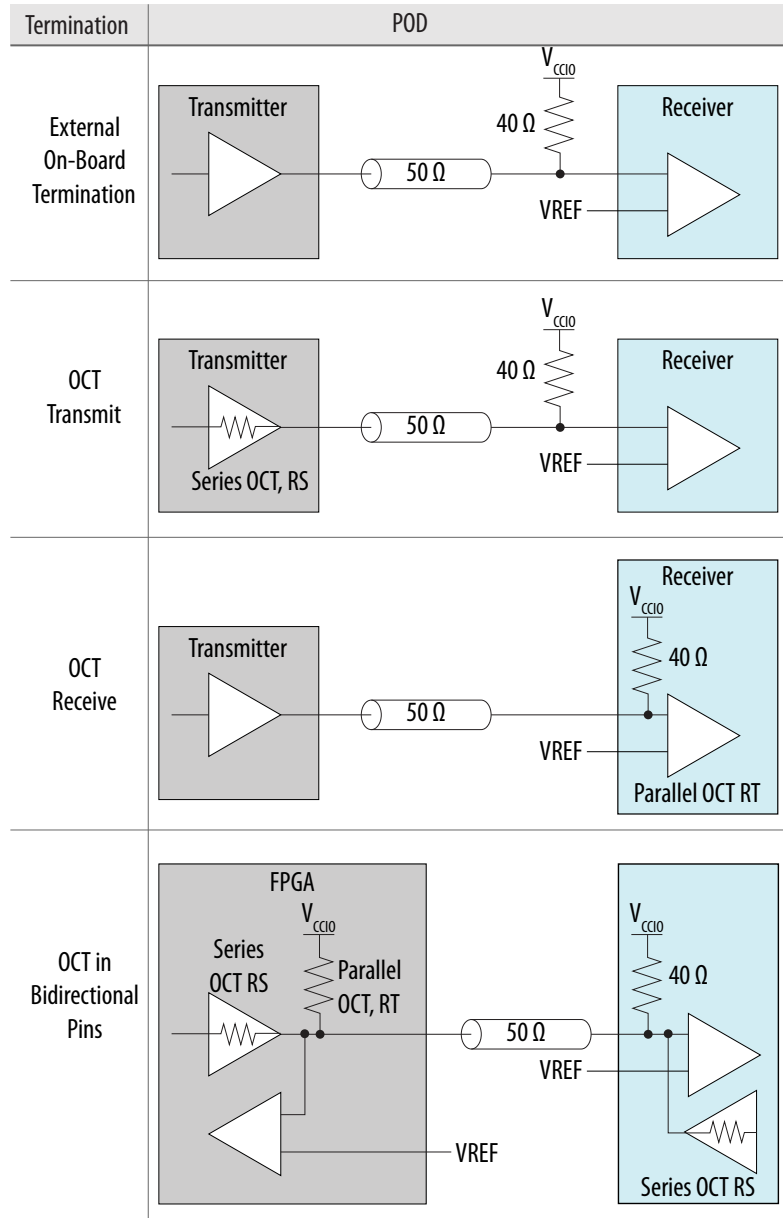


Figure 14. POD I/O Standard Termination

This figure shows the details of POD I/O termination on the Intel Stratix 10 devices.



Related Information

[Dynamic OCT on page 26](#)

2.5.2. Differential I/O Termination for Intel Stratix 10 Devices

The I/O pins are organized in pairs to support differential I/O standards. Each I/O pin pair can support differential input and output buffers.



The supported I/O standards such as Differential SSTL-12, Differential SSTL-15, Differential SSTL-125, and Differential SSTL-135 typically do not require external board termination.

Intel recommends that you use OCT with these I/O standards to save board space and cost. OCT reduces the number of external termination resistors used.

2.5.2.1. Differential HSTL, SSTL, HSUL, and POD Termination

Differential HSTL, SSTL, HSUL, and POD inputs use LVDS differential input buffers. However, R_D support is only available if the I/O standard is LVDS.

Differential HSTL, SSTL, HSUL, and POD outputs are not true differential outputs. These I/O standards use two single-ended outputs with the second output programmed as inverted.

Figure 15. Differential SSTL I/O Standard Termination

This figure shows the details of Differential SSTL I/O termination on Intel Stratix 10 devices.

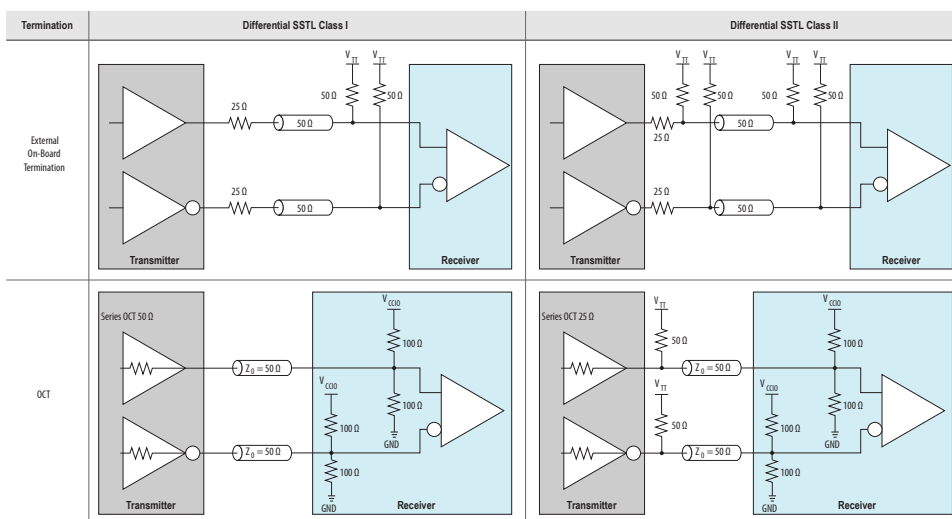


Figure 16. Differential HSTL I/O Standard Termination

This figure shows the details of Differential HSTL I/O standard termination on Intel Stratix 10 devices.

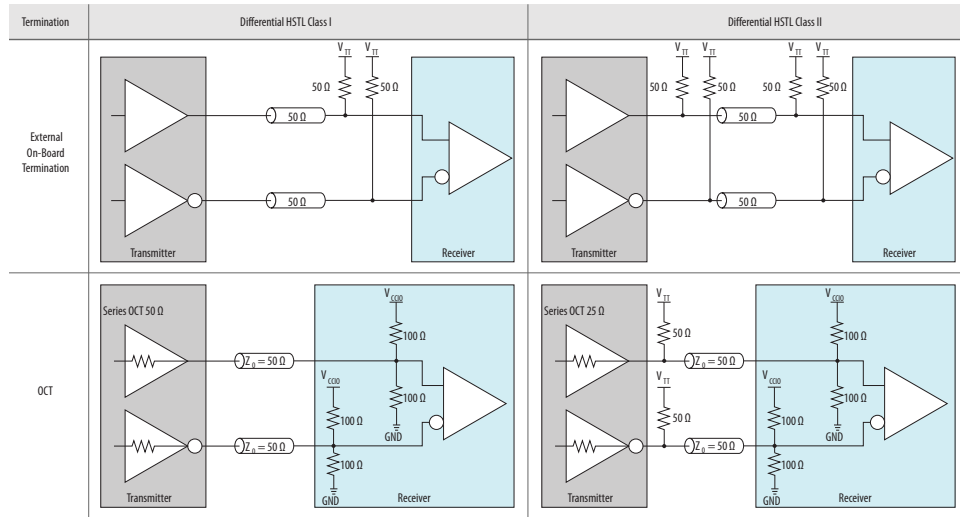
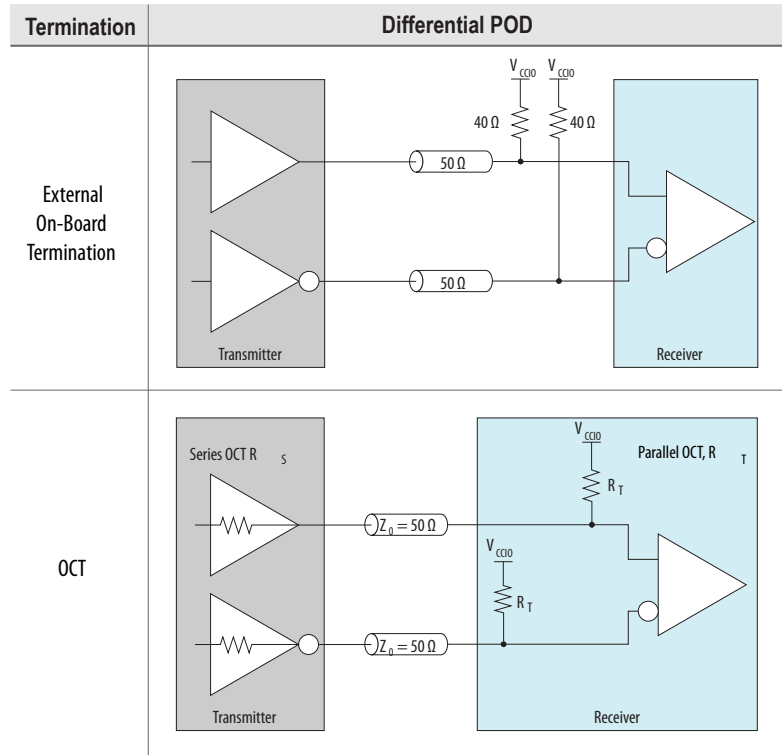


Figure 17. Differential POD I/O Standard Termination

This figure shows the details of Differential POD I/O termination on the Intel Stratix 10 devices.



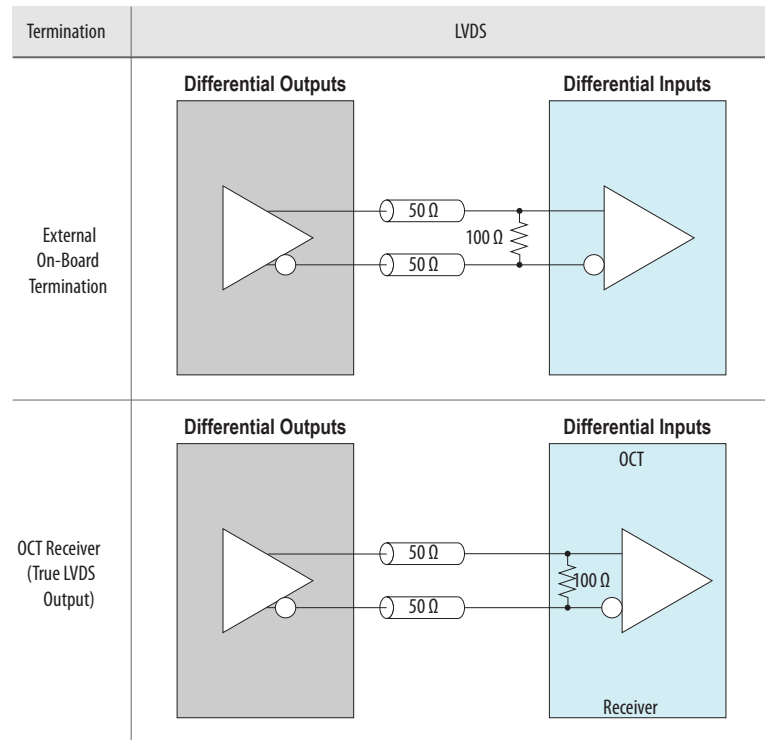
2.5.2.2. LVDS, RSDS, and Mini-LVDS Termination

All I/O banks have dedicated circuitry to support the true LVDS, RSDS, and mini-LVDS I/O standards by using true LVDS output buffers without resistor networks.



Figure 18. LVDS I/O Standard Termination

This figure shows the LVDS I/O standard termination. The on-chip differential resistor is available in all I/O banks.



2.5.2.3. LVPECL Termination

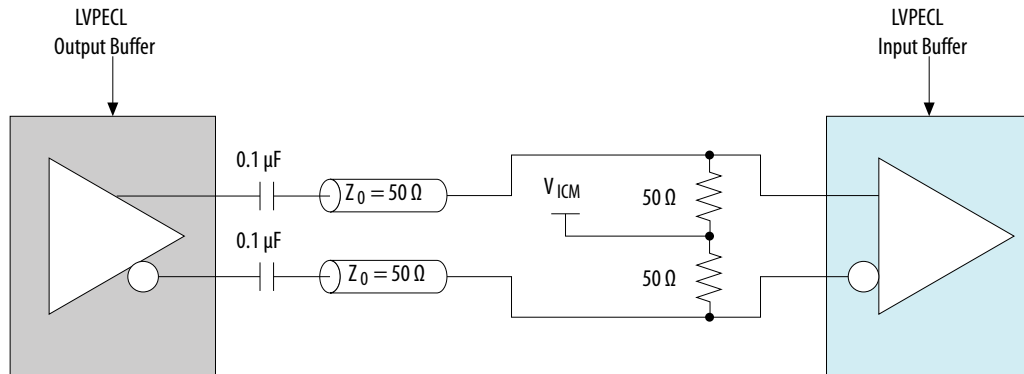
The Intel Stratix 10 devices support the LVPECL I/O standard on input clock pins only:

- LVPECL input operation is supported using LVDS input buffers.
- LVPECL output operation is not supported.

Use AC coupling if the LVPECL common-mode voltage of the output buffer does not match the LVPECL input common-mode voltage.

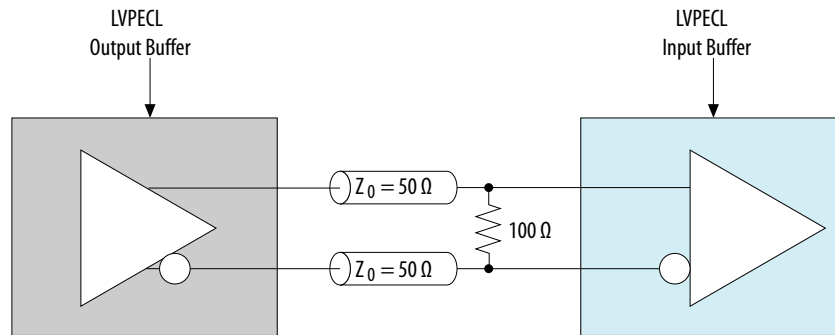
Note: Intel recommends that you use IBIS models to verify your LVPECL AC/DC-coupled termination.

Figure 19. LVPECL AC-Coupled External Termination



Support for DC-coupled LVPECL is available if the LVPECL output common mode voltage is within the Intel Stratix 10 LVPECL input buffer specification.

Figure 20. LVPECL DC-Coupled External Termination



For information about the V_{ICM} specification, refer to the device datasheet.

3. Intel Stratix 10 I/O Design Considerations

There are several considerations that require your attention to ensure the success of your designs. Unless noted otherwise, these design guidelines apply to all variants of this device family.

3.1. Guideline: V_{REF} Sources and V_{REF} Pins

For Intel Stratix 10 devices, consider the following V_{REF} pins guidelines:

- Intel Stratix 10 devices support internal and external V_{REF} sources.
 - There is an external V_{REF} pin for every I/O bank, providing one external V_{REF} source for all I/Os in the same bank.
 - Each I/O lane in the bank also has its own internal V_{REF} generator. You can configure each I/O lane independently to use its internal V_{REF} or the I/O bank's external V_{REF} source. All I/O pins in the same I/O lane use the same V_{REF} source.
- You can use the internal V_{REF} with calibration to support DDR4 using the POD12 I/O standard.
- You can place any combination of input, output, or bidirectional pins near V_{REF} pins. There is no V_{REF} pin placement restriction.
- The V_{REF} pins are dedicated for voltage-referenced single-ended I/O standards. You cannot use the V_{REF} pins as user I/Os.
- Connect unused V_{REF} pins to V_{CCIO} or GND .

For more information about pin capacitance of the V_{REF} pins, refer to the device datasheet.

Related Information

- [Intel Stratix 10 Device Datasheet](#)
- [Intel Stratix 10 Pin Connection Guidelines](#)
- [Pin-Out Files for Intel Stratix 10 Devices](#)
Provides the location of the V_{REF} and V_{CCIO} pins in different Intel Stratix 10 devices and packages.

3.2. Guideline: Observe Device Absolute Maximum Rating for 3.0 V Interfacing

To ensure device reliability and proper operation when you use the device for 3.0 V I/O interfacing, do not violate the absolute maximum ratings of the device. For more information about absolute maximum rating and maximum allowed overshoot during transitions, refer to the device datasheet.

Tip: Perform IBIS or SPICE simulations to make sure the overshoot and undershoot voltages are within the specifications.

Single-Ended Transmitter Application

If you use the Intel Stratix 10 device as a transmitter, use slow slew rate and series termination to limit the overshoot and undershoot at the I/O pins. Transmission line effects that cause large voltage deviations at the receiver are associated with an impedance mismatch between the driver and the transmission lines. By matching the impedance of the driver to the characteristic impedance of the transmission line, you can significantly reduce overshoot voltage. You can use a series termination resistor placed physically close to the driver to match the total driver impedance to the transmission line impedance.

Single-Ended Receiver Application

If you use the Intel Stratix 10 device as a receiver, use an external clamping diode to limit the overshoot and undershoot voltage at the I/O pins.

The 3.0 V I/O standard is supported using the bank supply voltage (V_{CCIO}) at 3.0 V and a V_{CCPT} voltage of 1.8 V. In this method, the clamping diode can sufficiently clamp overshoot voltage to within the DC and AC input voltage specifications. The clamped voltage is expressed as the sum of the V_{CCIO} and the diode forward voltage.

Related Information

- [Intel FPGA IBIS Models](#)
- [SPICE Models for Intel FPGA Devices](#)

3.3. Guideline: Voltage-Referenced and Non-Voltage Referenced I/O Standards

Each I/O bank can simultaneously support multiple I/O standards. Follow these guidelines if you use both non-voltage-referenced and voltage-referenced I/O standards in an I/O bank.

Non-Voltage-Referenced I/O Standards

An I/O bank can simultaneously support any number of input signals with different I/O standard assignments if the I/O standards support the V_{CCIO} level of the I/O bank.

For output signals, a single I/O bank supports non-voltage-referenced output signals that drive at the same voltage as V_{CCIO} . Because an I/O bank can only have one V_{CCIO} value, it can only drive out the value for non-voltage-referenced signals.

Voltage-Referenced I/O Standards

To accommodate voltage-referenced I/O standards:

- Each Intel Stratix 10 FPGA I/O bank contains a dedicated V_{REF} pin.
- Each bank can have only a single V_{CCIO} voltage level and a single voltage reference (V_{REF}) level.



The voltage-referenced input buffer is powered by V_{CCPT} . Therefore, an I/O bank featuring single-ended or differential standards can support different voltage-referenced standards under the following conditions:

- The V_{REF} are the same levels.
- On-chip parallel termination (R_T OCT) is disabled.

If you enable R_T OCT, the voltage for the input standard and the V_{CCIO} of the bank must match.

This feature allows you to place voltage-referenced input signals in an I/O bank with a V_{CCIO} of 1.8 V or below. For example, you can place HSTL-15 input pins in an I/O bank with 1.8 V V_{CCIO} . However, the voltage-referenced input with R_T OCT enabled requires the V_{CCIO} of the I/O bank to match the voltage of the input standard. R_T OCT cannot be supported for the HSTL-15 I/O standard when V_{CCIO} is 1.8 V.

Voltage-referenced bidirectional and output signals must be the same as the V_{CCIO} voltage of the I/O bank. For example, you can place only SSTL-18 output pins in an I/O bank with a 1.8 V V_{CCIO} .

Mixing Voltage-Referenced and Non-Voltage Referenced I/O Standards

An I/O bank can support voltage-referenced and non-voltage-referenced pins by applying each of the rule sets individually.

Examples:

- An I/O bank can support SSTL-18 inputs and outputs, and 1.8 V inputs and outputs with a 1.8 V V_{CCIO} and a 0.9 V V_{REF} .
- An I/O bank can support 1.5 V standards, 1.8 V inputs (but not outputs), and 1.5 V HSTL I/O standards with a 1.5 V V_{CCIO} and 0.75 V V_{REF} .

3.4. Guideline: Do Not Drive I/O Pins During Power Sequencing

The Intel Stratix 10 I/O buffers are powered by V_{CC} , V_{CCPT} , and V_{CCIO} .

Because the Intel Stratix 10 devices do not support hot socketing, do not drive the I/O pins externally during power up and power down. This includes all I/O pins including FPGA and HPS I/Os. Adhere to this guideline to:

- Avoid excess I/O pin current:
 - Excess I/O pin current affects the device's lifetime and reliability.
 - Excess current on the 3 V I/O pins can damage the Intel Stratix 10 device.
- Achieve minimum current draw and avoid I/O glitch during power up or power down.
- Avoid permanent damage on the 3 V I/O buffers in 3 V operation.

Related Information

[Power-Up and Power-Down Sequences, Intel Stratix 10 Power Management User Guide](#)



3.5. Guideline: Maximum DC Current Restrictions

There are no restrictions on the maximum DC current of any 10 consecutive I/O pins for Intel Stratix 10 devices.

Intel Stratix 10 devices conform to the V_{CCIO} Electro-Migration (EM) rule and IR drop targets for all I/O standard drive strength settings—ensuring reliability over the lifetime of the devices.



4. Intel Stratix 10 I/O Implementation Guides

You can implement your I/O design in the Intel Quartus Prime software. The software contains tools for you to create and compile your design, and configure your device.

The Intel Quartus Prime software allows you to prepare for device migration, set pin assignments, define placement restrictions, setup timing constraints, and customize IP cores. For more information about using the Intel Quartus Prime software, refer to the related information.

Related Information

- [Intel Quartus Prime Design Software](#)
Provides more information about using Intel Quartus Prime software.
- [IP Migration to the GPIO IP Core](#) on page 54
- [Introduction to Intel FPGA IP Cores](#)
Provides general information about all Intel FPGA IP cores, including parameterizing, generating, upgrading, and simulating IP cores.
- [Creating Version-Independent IP and Qsys Simulation Scripts](#)
Create simulation scripts that do not require manual updates for software or IP version upgrades.
- [Project Management Best Practices](#)
Guidelines for efficient management and portability of your project and IP files.

4.1. GPIO Intel FPGA IP

The GPIO IP core supports the GPIO components and features of the Intel Stratix 10 device family. You can use the Intel Quartus Prime parameter editor to configure the GPIO IP core.

Components of the GPIO IP core:

- Double data rate input/output (DDIO)—doubles or halves the data-rate of a communication channel
- Delay chains—configure the delay chains to perform specific delay and assist in I/O timing closure
- I/O buffers—connect the pads to the FPGA

Note: The 3 V I/O banks in Intel Stratix 10 devices do not support the DDIO feature of the GPIO IP core. Bypass the DDIO if you use an I/O standard supported only by 3 V I/O banks, such as 3.0 V LVCMOS. To bypass the DDIO feature, set the **Register mode** of the GPIO IP core to **none**.

4.1.1.1. GPIO Intel FPGA IP Data Paths

Figure 21. High-Level View of Single-Ended GPIO

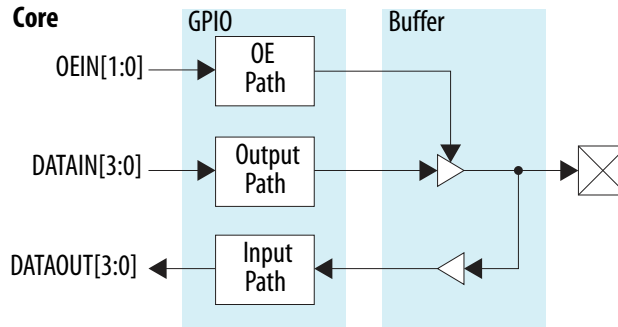


Table 16. GPIO IP Core Data Path Modes

| Data Path | Register Mode | | | |
|---------------|--|---|--|---|
| | Bypass | Simple Register | DDR I/O | |
| | | | Full-Rate | Half-Rate |
| Input | Data goes from the delay element to the core, bypassing all double data rate I/Os (DDIOs). | The full-rate DDIO operates as a simple register, bypassing half-rate DDIOs. The Fitter chooses whether to pack the register in the I/O or implement the register in the core, depending on the area and timing trade-offs. | The full-rate DDIO operates as a regular DDIO, bypassing the half-rate DDIOs. | The full-rate DDIO operates as a regular DDIO. The half-rate DDIOs convert full-rate data to half-rate data. |
| Output | Data goes from the core straight to the delay element, bypassing all DDIOs. | The full-rate DDIO operates as a simple register, bypassing half-rate DDIOs. The Fitter chooses whether to pack the register in the I/O or implement the register in the core, depending on the area and timing trade-offs. | The full-rate DDIO operates as a regular DDIO, bypassing the half-rate DDIOs. | The full-rate DDIO operates as a regular DDIO. The half-rate DDIOs convert full-rate data to half-rate data. |
| Bidirectional | The output buffer drives both an output pin and an input buffer. | The full-rate DDIO operates as a simple register. The output buffer drives both an output pin and an input buffer. | The full-rate DDIO operates as a regular DDIO. The output buffer drives both an output pin and an input buffer. The input buffer drives a set of three flip-flops. | The full-rate DDIO operates as a regular DDIO. The half-rate DDIOs convert full-rate data to half-rate. The output buffer drives both an output pin and an input buffer. The input buffer drives a set of three flip-flops. |

If you use asynchronous clear and preset signals, all DDIOs share these same signals.

Half-rate and full-rate DDIOs connect to separate clocks. When you use half-rate and full-rate DDIOs, the full-rate clock must run at twice the half-rate frequency. You can use different phase relationships to meet timing requirements.

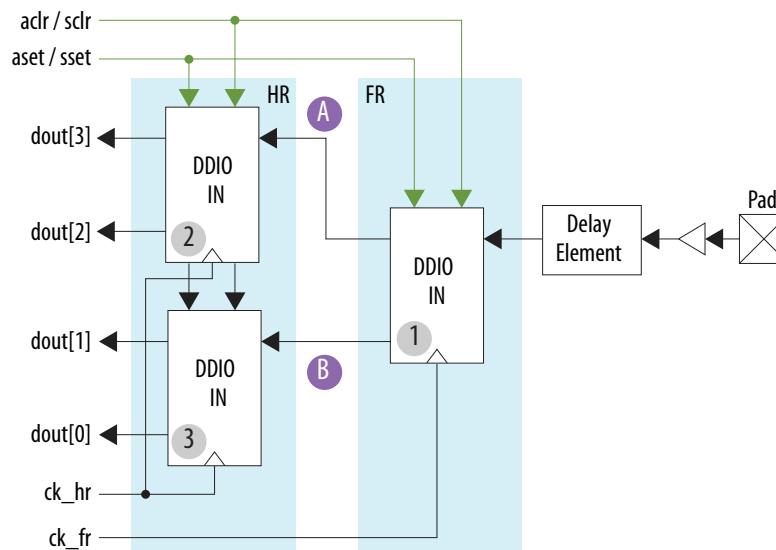


4.1.1.1. Input Path

The pad sends data to the input buffer, and the input buffer feeds the delay element. After the data goes to the output of the delay element, the programmable bypass multiplexers select the features and paths to use. Each LVDS I/O input path contains two stages of DDIOs, which are full-rate and half-rate.

The 3 V I/Os do not support DDIOs.

Figure 22. Simplified View of Single-Ended GPIO Input Path

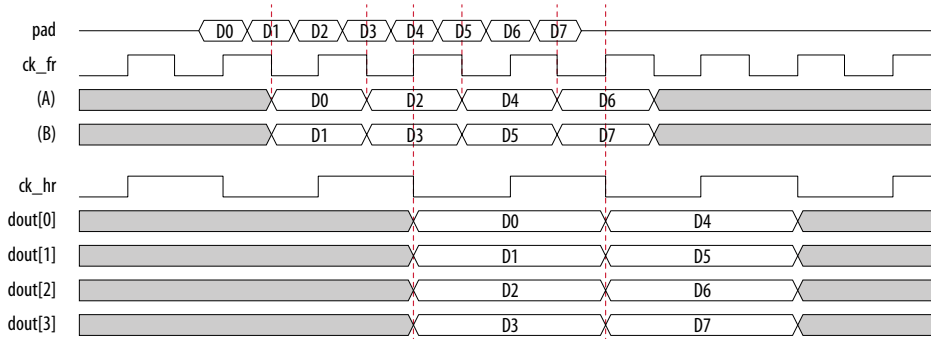


1. The pad receives data.
2. DDIO IN (1) captures data on the rising and falling edges of ck_fr and sends the data, signals (A) and (B) in the following waveform figure, at single data rate.
3. DDIO IN (2) and DDIO IN (3) halve the data rate.
4. $dout[3:0]$ presents the data as a half-rate bus.

Figure 23. Input Path Waveform in DDIO Mode with Half-Rate Conversion

In this figure, the data goes from full-rate clock at double data rate to half-rate clock at single data rate. The data rate is divided by four and the bus size is increased by the same ratio. The overall throughput through the GPIO IP core remains unchanged.

The actual timing relationship between different signals may vary depending on the specific design, delays, and phases that you choose for the full-rate and half-rate clocks.



Note: The GPIO IP core does not support dynamic calibration of bidirectional pins. For applications that require dynamic calibration of bidirectional pins, refer to the related information.

Related Information

- [PHY Lite for Parallel Interfaces Intel FPGA IP Core User Guide: Intel Stratix 10, Intel Arria® 10, and Intel Cyclone® 10 GX Devices](#)
Provides more information for applications that require dynamic OCT for bidirectional pins.
- [Output and Output Enable Paths](#) on page 44

4.1.1.2. Output and Output Enable Paths

The output delay element sends data to the pad through the output buffer.

Each LVDS I/O output path contains two stages of DDIOs, which are half-rate and full-rate.

The 3 V I/Os do not support DDIOs.

Figure 24. Simplified View of Single-Ended GPIO Output Path

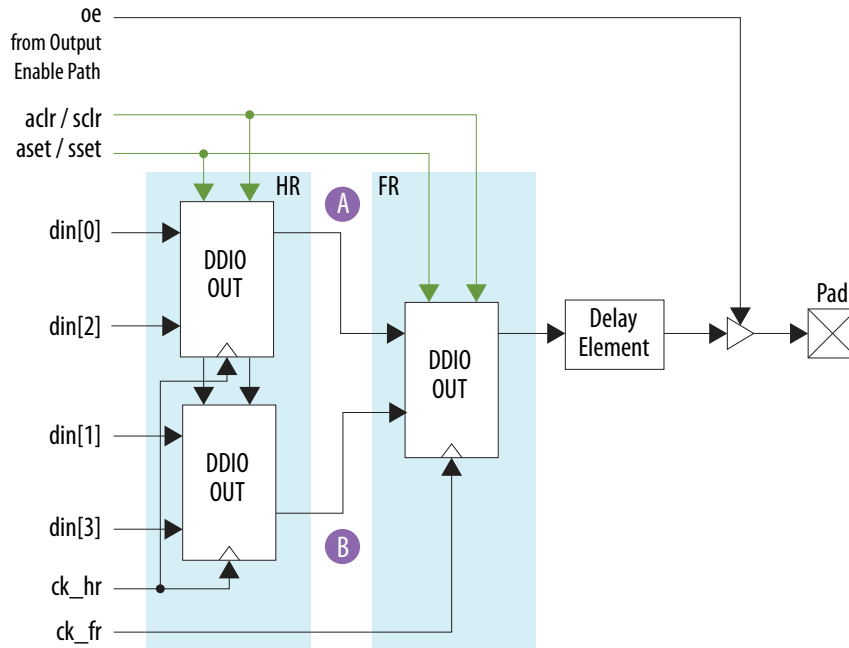


Figure 25. Output Path Waveform in DDIO Mode with Half-Rate Conversion

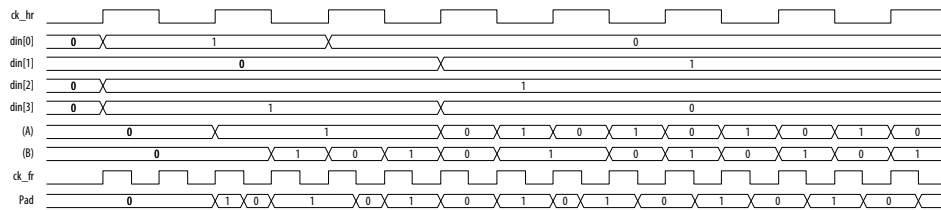
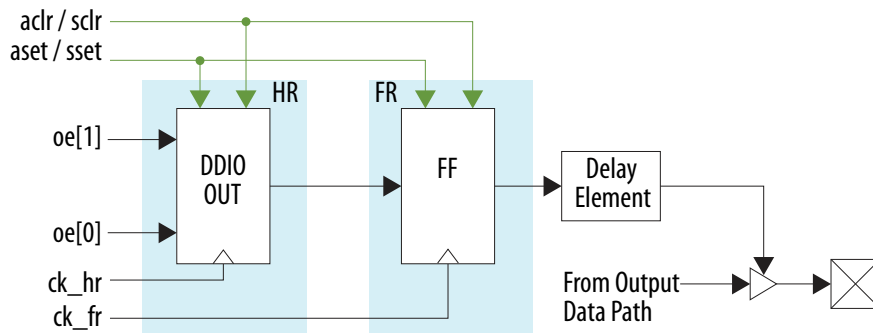


Figure 26. Simplified View of Output Enable Path



The difference between the output path and output enable (OE) path is that the OE path does not contain full-rate DDIO. To support packed-register implementations in the OE path, a simple register operates as full-rate DDIO. For the same reason, only one half-rate DDIO is present.

The OE path operates in the following three fundamental modes:

- Bypass—the core sends data directly to the delay element, bypassing all DDIOs.
- Packed Register—bypasses half-rate DDIO.
- SDR output at half-rate—half-rate DDIOs convert data from full-rate to half-rate.

In Intel Stratix 10 devices, each 3 V I/O bank supports only two output enables (OE) for its eight single-ended I/Os.

Note: The GPIO IP core does not support dynamic calibration of bidirectional pins. For applications that require dynamic calibration of bidirectional pins, refer to the related information.

Related Information

- [PHY Lite for Parallel Interfaces Intel FPGA IP Core User Guide: Intel Stratix 10, Intel Arria® 10, and Intel Cyclone® 10 GX Devices](#)
Provides more information for applications that require dynamic OCT for bidirectional pins.
- [Input Path](#) on page 43

4.1.2. Register Packing

The GPIO IP core allows you to pack register into the periphery to save area and resource utilization.

You can configure the full-rate DDIO on the input and output path as a flip flop. To do so, add the .qsf assignments listed in this table.

Table 17. Register Packing QSF Assignments

| Path | QSF Assignment |
|--------------------------------|--|
| Input register packing | <code>set_instance_assignment -name FAST_INPUT_REGISTER ON -to <path to register></code> |
| Output register packing | <code>set_instance_assignment -name FAST_OUTPUT_REGISTER ON -to <path to register></code> |
| Output enable register packing | <code>set_instance_assignment -name FAST_OUTPUT_ENABLE_REGISTER ON -to <path to register></code> |

Note: These assignments do not guarantee register packing. However, these assignments enable the Fitter to find a legal placement. Otherwise, the Fitter keeps the flip flop in the core.

4.2. Verifying Resource Utilization and Design Performance

You can refer to the Intel Quartus Prime compilation reports to get details about the resource usage and performance of your design.

1. On the menu, click **Processing** > **Start Compilation** to run a full compilation.
2. After compiling the design, click **Processing** > **Compilation Report**.
3. Using the **Table of Contents**, navigate to **Fitter** > **Resource Section**.
 - a. To view the resource usage information, select **Resource Usage Summary**.



- b. To view the resource utilization information, select **Resource Utilization by Entity**.

4.3. GPIO Intel FPGA IP Timing

The performance of the GPIO IP core depends on the I/O constraints and clock phases. To validate the timing for your GPIO configuration, Intel recommends that you use the Timing Analyzer.

Related Information

[The Intel Quartus Prime Timing Analyzer](#)

4.3.1. Timing Components

The GPIO IP core timing components consist of three paths.

- I/O interface paths—from the FPGA to external receiving devices and from external transmitting devices to the FPGA.
- Core interface paths of data and clock—from the I/O to the core and from the core to I/O.
- Transfer paths—from half-rate to full-rate DDIO, and from full-rate to half-rate DDIO.

Note: The Timing Analyzer treats the path inside the DDIO_IN and DDIO_OUT blocks as black boxes.

Figure 27. Input Path Timing Components

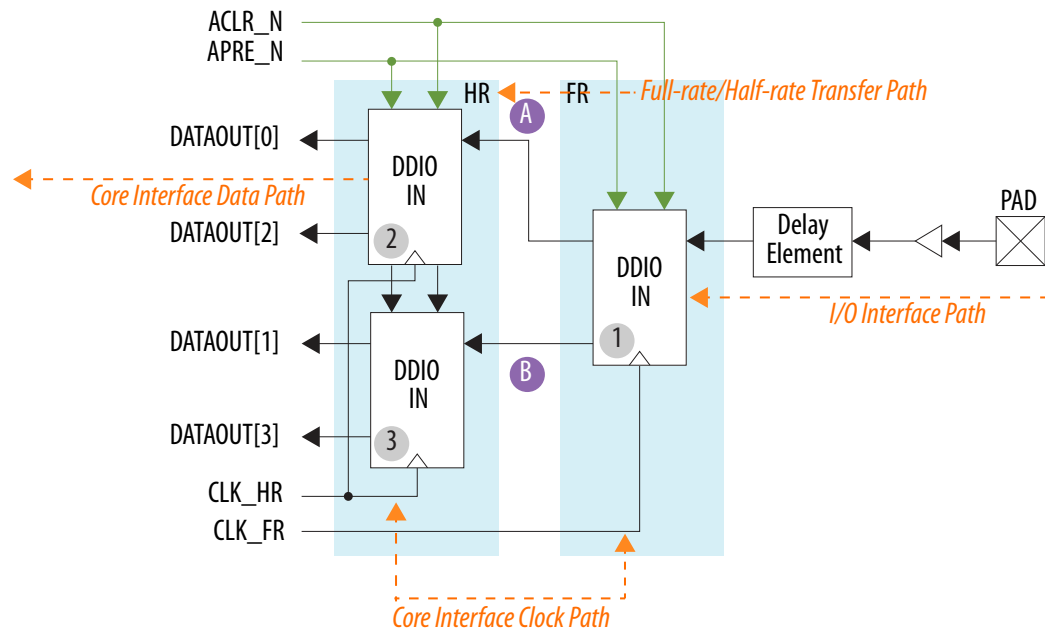


Figure 28. Output Path Timing Components

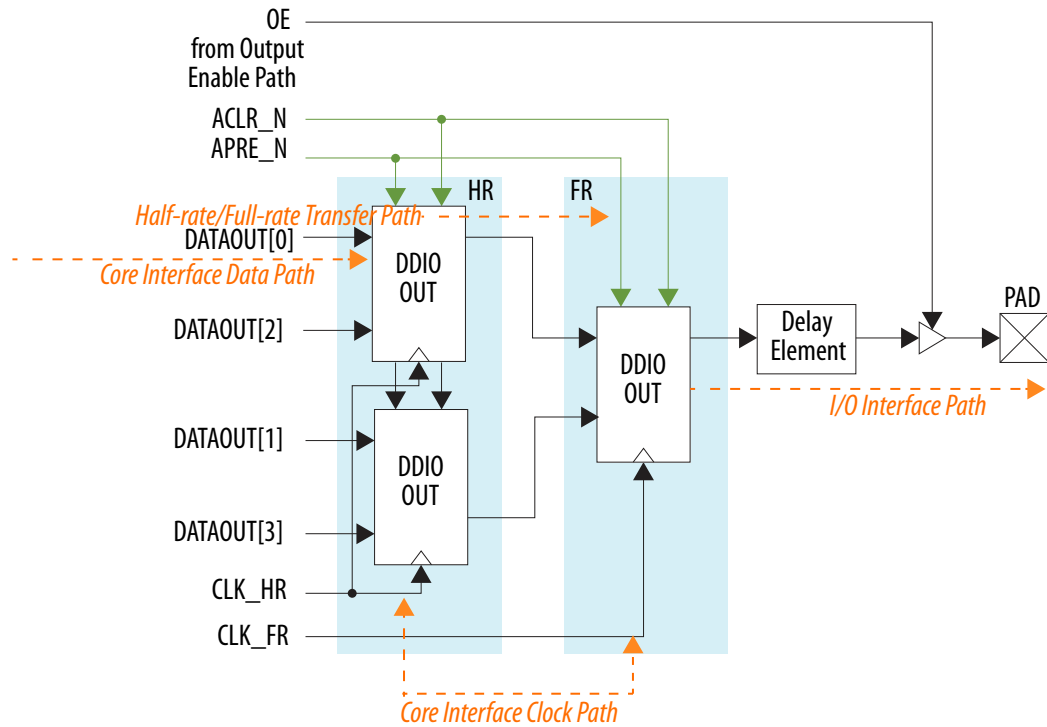
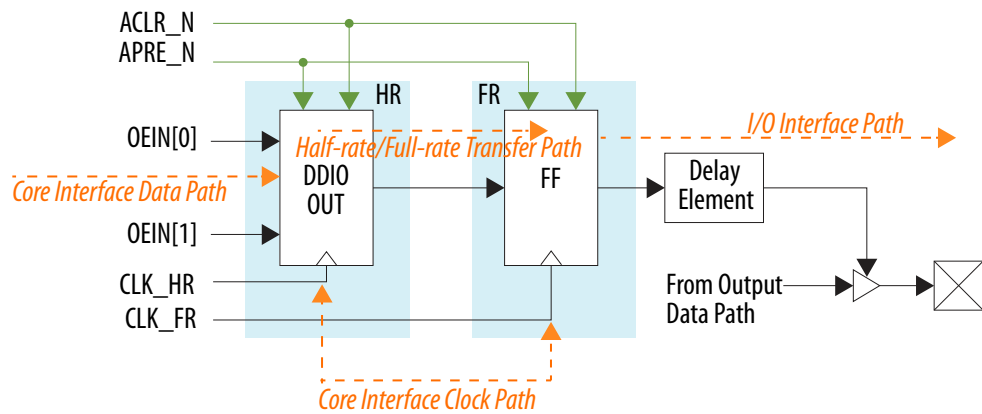


Figure 29. Output Enable Path Timing Components





4.3.2. Delay Elements

The Intel Quartus Prime software does not automatically set delay elements to maximize slack in the I/O timing analysis. To close the timing or maximize slack, set the delay elements manually in the Intel Quartus Prime settings file (.qsf).

Table 18. Delay Elements .qsf Assignments

Specify these assignments in the .qsf to access the delay elements.

| Delay Element | .qsf Assignment |
|-----------------------------|---|
| Input Delay Element | <code>set_instance_assignment -to <PIN> -name INPUT_DELAY_CHAIN <0..63></code> |
| Output Delay Element | <code>set_instance_assignment -to <PIN> -name OUTPUT_DELAY_CHAIN <0..15></code> |
| Output Enable Delay Element | <code>set_instance_assignment -to <PIN> -name OE_DELAY_CHAIN <0..15></code> |

4.3.3. Timing Analysis

The Intel Quartus Prime software does not automatically generate the SDC timing constraints for the GPIO IP core. You must manually enter the timing constraints.

Follow the timing guidelines and examples to ensure that the Timing Analyzer analyzes the I/O timing correctly.

- To perform proper timing analysis for the I/O interface paths, specify the system level constraints of the data pins against the system clock pin in the .sdc file.
- To perform proper timing analysis for the core interface paths, define these clock settings in the .sdc file:
 - Clock to the core registers
 - Clock to the I/O registers for the simple register and DDIO modes

Related Information

[AN 433: Constraining and Analyzing Source-Synchronous Interfaces](#)

Describes techniques for constraining and analyzing source-synchronous interfaces.

4.3.3.1. Single Data Rate Input Register

Figure 30. Single Data Rate Input Register

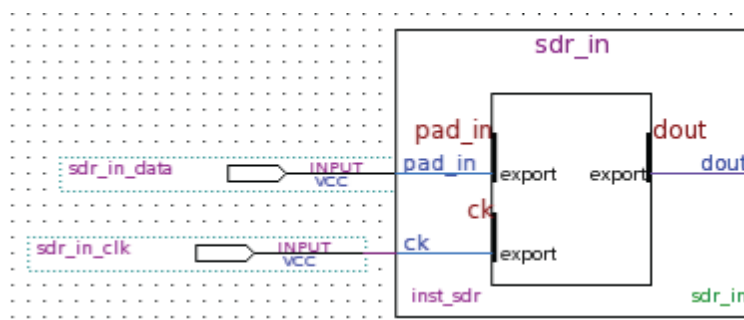


Table 19. Single Data Rate Input Register .sdc Command Examples

| Command | Command Example | Description |
|-----------------|--|--|
| create_clock | create_clock -name sdr_in_clk -period "100 MHz" sdr_in_clk | Creates clock setting for the input clock. |
| set_input_delay | set_input_delay -clock sdr_in_clk 0.15 sdr_in_data | Instructs the Timing Analyzer to analyze the timing of the input I/O with a 0.15 ns input delay. |

4.3.3.2. Full-Rate or Half-Rate DDIO Input Register

The input side of the full-rate and half-rate DDIO input registers are the same. You can properly constrain the system by using a virtual clock to model the off-chip transmitter to the FPGA.

Figure 31. Full-Rate or Half-Rate DDIO Input Register

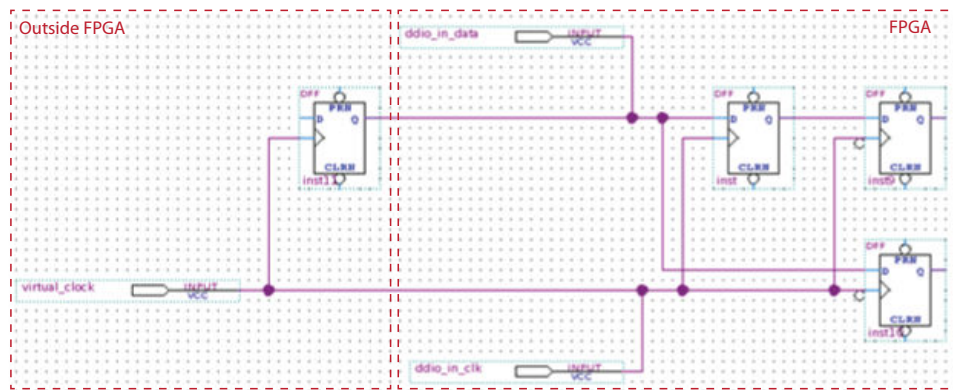


Table 20. Full-Rate or Half-Rate DDIO Input Register .sdc Command Examples

| Command | Command Example | Description |
|-----------------|---|---|
| create_clock | create_clock -name virtual_clock -period "200 MHz" create_clock -name ddiio_in_clk -period "200 MHz" ddiio_in_clk | Create clock setting for the virtual clock and the DDIO clock. |
| set_input_delay | set_input_delay -clock virtual_clock 0.25 ddiio_in_data set_input_delay -add_delay -clock_fall -clock virtual_clock 0.25 ddiio_in_data | Instruct the Timing Analyzer to analyze the positive clock edge and the negative clock edge of the transfer. Note the -add_delay in the second set_input_delay command. |
| set_false_path | set_false_path -fall_from virtual_clock -rise_to ddiio_in_clk set_false_path -rise_from virtual_clock -fall_to ddiio_in_clk | Instruct the Timing Analyzer to ignore the positive clock edge to the negative edge triggered register, and the negative clock edge to the positive edge triggered register. <i>Note:</i> The ck_hr frequency must be half the ck_fr frequency. If the I/O PLL drives the clocks, you can consider using the derive_pll_clocks .sdc command. |



4.3.3.3. Single Data Rate Output Register

Figure 32. Single Data Rate Output Register

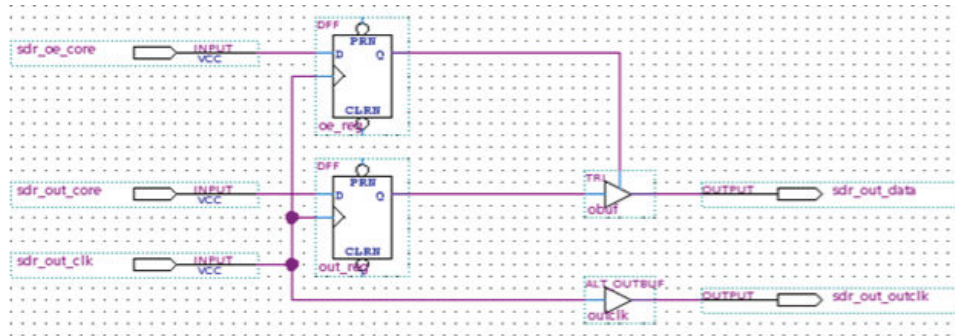


Table 21. Single Data Rate Output Register .sdc Command Examples

| Command | Command Example | Description |
|---|--|--|
| create_clock and create_generated_clock | create_clock -name sdr_out_clk -period "100 MHz" sdr_out_clk create_generated_clock -source sdr_out_clk -name sdr_out_outclk sdr_out_outclk | Generate the source clock and the output clock to transmit. |
| set_output_delay | set_output_delay -clock sdr_out_clk 0.45 sdr_out_data | Instructs the Timing Analyzer to analyze the output data to transmit against the output clock to transmit. |

4.3.3.4. Full-Rate or Half-Rate DDIO Output Register

The output side of the full-rate and half-rate DDIO output registers are the same.

Table 22. DDIO Output Register .sdc Command Examples

| Command | Command Example | Description |
|---|--|---|
| create_clock and create_generated_clock | create_clock -name ddio_out_fr_clk -period "200 MHz" ddio_out_fr_clk create_generated_clock -source ddio_out_fr_clk -name ddio_out_fr_outclk ddio_out_fr_outclk | Generate the clocks to the DDIO and the clock to transmit. |
| set_output_delay | set_output_delay -clock ddio_out_fr_outclk 0.55 ddio_out_fr_data set_output_delay -add_delay -clock_fall -clock ddio_out_fr_outclk 0.55 ddio_out_fr_data | Instruct the Timing Analyzer to analyze the positive and negative data against the output clock. |
| set_false_path | set_false_path -rise_from ddio_out_fr_clk -fall_to ddio_out_fr_outclk set_false_path -fall_from ddio_out_fr_clk -rise_to ddio_out_fr_outclk | Instruct the Timing Analyzer to ignore the rising edge of the source clock against the falling edge of the output clock, and the falling edge of source clock against rising edge of output clock |

4.3.4. Timing Closure Guidelines

For the GPIO input registers, the input I/O transfer is likely to fail the hold time if you do not set the input delay chain. This failure is caused by the clock delay being larger than the data delay.

To meet the hold time, add delay to the input data path using the input delay chain. In general, the input delay chain is around 30 ps per step at the -1 speed grade. To get an approximate input delay chain setting to pass the timing, divide the negative hold slack by 60 ps.

However, if the I/O PLL drives the clocks of the GPIO input registers (simple register or DDIO mode), you can set the compensation mode to source synchronous mode. The Fitter will attempt to configure the I/O PLL for a better setup and hold slack for the input I/O timing analysis.

For the GPIO output and output enable registers, you can add delay to the output data and clock using the output and output enable delay chains.

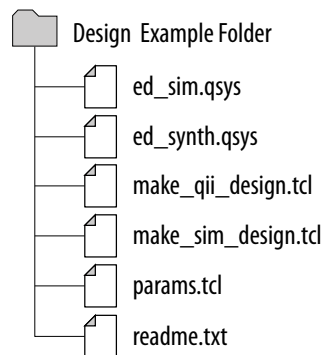
- If you observe setup time violation, you can increase the output clock delay chain setting.
- If you observe hold time violation, you can increase the output data delay chain setting.

4.4. GPIO Intel FPGA IP Design Examples

The GPIO IP core can generate design examples that match your IP configuration in the parameter editor. You can use these design examples as references for instantiating the IP core and the expected behavior in simulations.

You can generate the design examples from the GPIO IP core parameter editor. After you have set the parameters that you want, click **Generate Example Design**. The IP core generates the design example source files in the directory you specify.

Figure 33. Source Files in the Generated Design Example Directory



Note: The `.qsys` files are for internal use during design example generation only. You cannot edit these `.qsys` files.



4.4.1. GPIO IP Core Synthesizable Intel Quartus Prime Design Example

The synthesizable design example is a compilation-ready Platform Designer system that you can include in an Intel Quartus Prime project.

Generating and Using the Design Example

To generate the synthesizable Intel Quartus Prime design example from the source files, run the following command in the design example directory:

```
quartus_sh -t make_qii_design.tcl
```

To specify an exact device to use, run the following command:

```
quartus_sh -t make_qii_design.tcl [device_name]
```

The TCL script creates a `qii` directory that contains the `ed_synth.qpf` project file. You can open and compile this project in the Intel Quartus Prime software.

4.4.2. GPIO IP Core Simulation Design Example

The simulation design example uses your GPIO IP core parameter settings to build the IP instance connected to a simulation driver. The driver generates random traffic and internally checks the legality of the out going data.

Using the design example, you can run a simulation using a single command, depending on the simulator that you use. The simulation demonstrates how you can use the GPIO IP core.

Generating and Using the Design Example

To generate the simulation design example from the source files for a Verilog simulator, run the following command in the design example directory:

```
quartus_sh -t make_sim_design.tcl
```

To generate the simulation design example from the source files for a VHDL simulator, run the following command in the design example directory:

```
quartus_sh -t make_sim_design.tcl VHDL
```

The TCL script creates a `sim` directory that contains subdirectories—one for each supported simulation tool. You can find the scripts for each simulation tool in the corresponding directories.

4.5. Verifying Pin Migration Compatibility

You can use the **Pin Migration View** window in the Intel Quartus Prime software Pin Planner to assist you in verifying whether your pin assignments migrate to a different device successfully. You can vertically migrate to a device with a different density while using the same device package, or migrate between packages with different densities and ball counts.

1. Open **Assignments > Pin Planner** and create pin assignments.
2. If necessary, perform one of the following options to populate the Pin Planner with the node names in the design:

- Analysis & Elaboration
 - Analysis & Synthesis
 - Fully compile the design
3. Then, on the menu, click **View > Pin Migration View**.
 4. To select or change migration devices:
 - a. Click **Device** to open the **Device** dialog box.
 - b. Under **Migration compatibility** click **Migration Devices**.
 5. To show more information about the pins:
 - a. Right-click anywhere in the **Pin Migration View** window and select **Show Columns**.
 - b. Then, click the pin feature you want to display.
 6. If you want to view only the pins, in at least one migration device, that have a different feature than the corresponding pin in the migration result, turn on **Show migration differences**.
 7. Click **Pin Finder** to open the **Pin Finder** dialog box to find and highlight pins with specific functionality.

If you want to view only the pins highlighted by the most recent query in the **Pin Finder** dialog box, turn on **Show only highlighted pins**.
 8. To export the pin migration information to a Comma-Separated Value file (**.csv**), click **Export**.

Related Information

[Intel Quartus Prime Design Software](#)

Provides more information about using Intel Quartus Prime software.

4.6. IP Migration to the GPIO IP Core

The GPIO IP core can migrate your GPIO IPs from previous devices to work in Intel Stratix 10 designs.

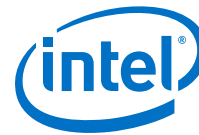
Depending on the mode you use in your previous IP, the IP migration tool can automatically configure the new GPIO IP core based on settings in your previous IP. For unsupported modes, you can use the GPIO IP core parameter editor to manually configure the migrated IP core.

4.6.1. Migrating Your ALTDDIO_IN, ALTDDIO_OUT, ALTDDIO_BIDIR, and ALTIobuf IP Cores

To migrate your ALTDDIO_IN, ALTDDIO_OUT, ALTDDIO_BIDIR, and ALTIobuf IP cores to the GPIO Intel FPGA IP IP core, follow these steps:

1. Open your ALTDDIO_IN, ALTDDIO_OUT, ALTDDIO_BIDIR, or ALTIobuf IP core in the IP Parameter Editor.
2. In the **Currently selected device family**, select **Stratix 10**.
3. Click **Finish** to open the GPIO IP Parameter Editor.

The IP Parameter Editor configures the GPIO IP core settings similar to the ALTDDIO_IN, ALTDDIO_OUT, ALTDDIO_BIDIR, or ALTIobuf core settings.



4. If there are any incompatible settings between the two, select **new supported settings**.
5. Click **Finish** to regenerate the IP core.
6. Replace your ALTDDIO_IN, ALTDDIO_OUT, ALTDDIO_BIDIR, or ALTIOBUF IP core instantiation in RTL with the GPIO IP core.

Note: The GPIO IP core port names may not match the ALTDDIO_IN, ALTDDIO_OUT, ALTDDIO_BIDIR, or ALTIOBUF IP core port names. Therefore, simply changing the IP core name in the instantiation may not be sufficient.

4.6.2. Guideline: Swap `datain_h` and `datain_l` Ports in Migrated IP

When you migrate your GPIO IP from previous devices to the GPIO IP core, you can turn on **Use legacy top-level port names** option in the GPIO IP core parameter editor. However, the behavior of these ports in the GPIO IP core is different than in the IP cores used for the Stratix V, Arria® V, and Cyclone® V devices.

The GPIO IP core drives these ports to the output registers on these clock edges:

- `datain_h`—on the falling edge of `outclock`
- `datain_l`—on the rising edge of `outclock`

If you migrated your GPIO IP from Stratix V, Arria V, and Cyclone V devices, swap the `datain_h` and `datain_l` ports when you instantiate the IP generated by the GPIO IP core.

5. GPIO Intel FPGA IP Reference

You can set various parameter settings for the GPIO Intel FPGA IP to customize its behaviors, ports, and signals.

The Intel Quartus Prime software generates your customized GPIO IP core according to the parameter options that you set in the IP parameter editor.

5.1. GPIO Intel FPGA IP Parameter Settings

You can set the parameter settings for the GPIO IP core in the Intel Quartus Prime software. There are three groups of options: **General**, **Buffer**, and **Registers**.

Table 23. GPIO IP Core Parameters - General

| Parameter | Condition | Allowed Values | Description |
|---------------------------------|-----------|--|--|
| Data Direction | — | <ul style="list-style-type: none"> Input Output Bidir | Specifies the data direction for the GPIO. |
| Data width | — | 1 to 128 | Specifies the data width. |
| Use legacy top-level port names | — | <ul style="list-style-type: none"> On Off | <p>Use same port names as in Stratix V, Arria V, and Cyclone V devices.</p> <p>For example, dout becomes dataout_h and dataout_l, and din becomes datain_h and datain_l.</p> <p><i>Note:</i> The behavior of these ports are different than in the Stratix V, Arria V, and Cyclone V devices. For the migration guideline, refer to the related information.</p> |

Table 24. GPIO IP Core Parameters - Buffer

| Parameter | Condition | Allowed Values | Description |
|--------------------------------|--|---|---|
| Use differential buffer | — | <ul style="list-style-type: none"> On Off | If turned on, enables differential I/O buffers. |
| Use pseudo differential buffer | <ul style="list-style-type: none"> Data Direction = Output Use differential buffer = On | <ul style="list-style-type: none"> On Off | <p>If turned on in output mode, enables pseudo differential output buffers.</p> <p>This option is automatically turned on for bidirectional mode if you turn on Use differential buffer.</p> |
| Use bus-hold circuitry | <ul style="list-style-type: none"> Data Direction = Input or Bidir Use differential buffer = Off | <ul style="list-style-type: none"> On Off | If turned on, the bus hold circuitry can weakly hold the signal on an I/O pin at its last-driven state where the output buffer state will be 1 or 0 but not high-impedance. |

continued...



| Parameter | Condition | Allowed Values | Description |
|--|---|---|---|
| Use open drain output | <ul style="list-style-type: none"> Data Direction = Output or Bidir Use differential buffer = Off | <ul style="list-style-type: none"> On Off | If turned on, the open drain output enables the device to provide system-level control signals such as interrupt and write enable signals that can be asserted by multiple devices in your system. |
| Enable output enable port | Data Direction = Output | <ul style="list-style-type: none"> On Off | <p>If turned on, enables user input to the OE port. This option is automatically turned on for bidirectional mode.</p> <p>In Intel Stratix 10 devices, each 3 V I/O bank supports only two output enables (OE) for its eight single-ended I/Os.</p> |
| Enable seriestermination / paralleltermination ports | — | <ul style="list-style-type: none"> On Off | If turned on, enables the seriesterminationcontrol and parallelterminationcontrol ports of the output buffer. |

Table 25. GPIO IP Core Parameters - Registers

| Parameter | Condition | Allowed Values | Description |
|---|--|---|---|
| Register mode | — | <ul style="list-style-type: none"> None Simple register DDIO | <p>Specifies the register mode for the GPIO IP core:</p> <ul style="list-style-type: none"> None—specifies a simple wire connection from/to the buffer. Simple register—specifies that the DDIO is used as a simple register in single data-rate mode (SDR). The Fitter may pack this register in the I/O. DDIO— specifies that the IP core uses the DDIO. <p>If you use an I/O standard supported only by the 3 V I/O banks, select None.</p> |
| Enable synchronous clear / preset port | <ul style="list-style-type: none"> Register mode = DDIO | <ul style="list-style-type: none"> None Clear Preset | <p>Specifies how to implement synchronous reset port.</p> <ul style="list-style-type: none"> None—Disables synchronous reset port. Clear—Enables the SCLR port for synchronous clears. Preset—Enables the SSET port for synchronous preset. |
| Enable asynchronous clear / preset port | <ul style="list-style-type: none"> Register mode = DDIO | <ul style="list-style-type: none"> None Clear Preset | <p>Specifies how to implement asynchronous reset port.</p> <ul style="list-style-type: none"> None—Disables asynchronous reset port. Clear—Enables the ACLR port for asynchronous clears. Preset—Enables the ASET port for asynchronous preset. <p>ACLR and ASET signals are active high.</p> |
| <i>continued...</i> | | | |

| Parameter | Condition | Allowed Values | Description |
|--------------------------------|---|---|---|
| Enable clock enable ports | Register mode = DDIO | <ul style="list-style-type: none"> On Off | <ul style="list-style-type: none"> On—exposes the clock enable (CKE) port to allow you to control when data is clocked in or out. This signal prevents data from being passed through without your control. Off—clock enable port is not exposed and data always pass through the register automatically. |
| Half Rate logic | Register mode = DDIO | <ul style="list-style-type: none"> On Off | If turned on, enables half-rate DDIO. |
| Separate input / output Clocks | <ul style="list-style-type: none"> Data Direction = Bidir Register mode = Simple register or DDIO | <ul style="list-style-type: none"> On Off | If turned on, enables separate clocks (CK_IN and CK_OUT) for the input and output paths in bidirectional mode. |

Related Information

Guideline: Swap `datain_h` and `datain_l` Ports in Migrated IP on page 55

5.2. GPIO Intel FPGA IP Interface Signals

Depending on parameter settings you specify, different interface signals are available for the GPIO IP core.

Figure 34. GPIO IP Core Interfaces



Figure 35. GPIO Interface Signals

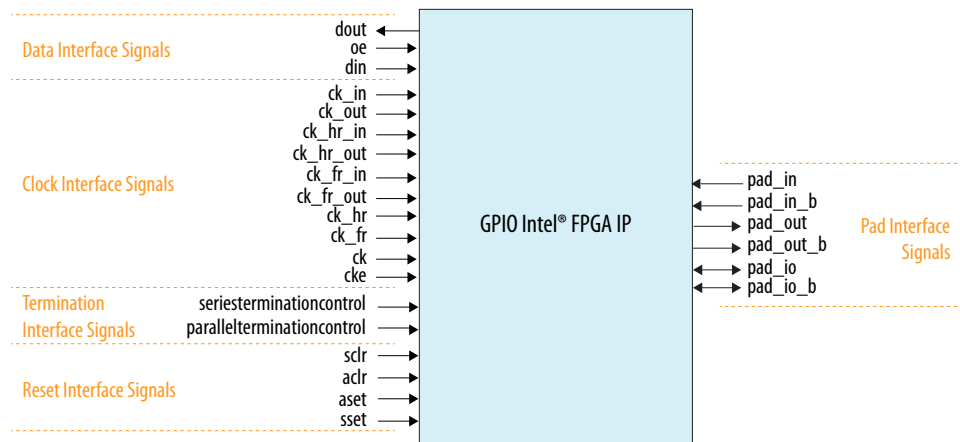




Table 26. Pad Interface Signals

The pad interface is the physical connection from the GPIO IP core to the pad. This interface can be an input, output or bidirectional interface, depending on the IP core configuration. In this table, *SIZE* is the data width specified in the IP core parameter editor.

| Signal Name | Direction | Description |
|------------------------------|---------------|--|
| pad_in[<i>SIZE</i> -1:0] | Input | Input signal from the pad. |
| pad_in_b[<i>SIZE</i> -1:0] | Input | Negative node of the differential input signal from the pad. This port is available if you turn on the Use differential buffer option. |
| pad_out[<i>SIZE</i> -1:0] | Output | Output signal to the pad. |
| pad_out_b[<i>SIZE</i> -1:0] | Output | Negative node of the differential output signal to the pad. This port is available if you turn on the Use differential buffer option. |
| pad_io[<i>SIZE</i> -1:0] | Bidirectional | Bidirectional signal connection with the pad. |
| pad_io_b[<i>SIZE</i> -1:0] | Bidirectional | Negative node of the differential bidirectional signal connection with the pad. This port is available if you turn on the Use differential buffer option. |

Table 27. Data Interface Signals

The data interface is an input or output interface from the GPIO IP core to the FPGA core. In this table, *SIZE* is the data width specified in the IP core parameter editor.

| Signal Name | Direction | Description |
|------------------------------|-----------|---|
| din[<i>DATA_SIZE</i> -1:0] | Input | Data input from the FPGA core in output or bidirectional mode. <i>DATA_SIZE</i> depends on the register mode: <ul style="list-style-type: none"> Bypass or simple register—<i>DATA_SIZE</i> = <i>SIZE</i> DDIO without half-rate logic—<i>DATA_SIZE</i> = 2 × <i>SIZE</i> DDIO with half-rate logic—<i>DATA_SIZE</i> = 4 × <i>SIZE</i> |
| dout[<i>DATA_SIZE</i> -1:0] | Output | Data output to the FPGA core in input or bidirectional mode, <i>DATA_SIZE</i> depends on the register mode: <ul style="list-style-type: none"> Bypass or simple register—<i>DATA_SIZE</i> = <i>SIZE</i> DDIO without half-rate logic—<i>DATA_SIZE</i> = 2 × <i>SIZE</i> DDIO with half-rate logic—<i>DATA_SIZE</i> = 4 × <i>SIZE</i> |
| oe[<i>OE_SIZE</i> -1:0] | Input | OE input from the FPGA core in output mode with Enable output enable port turned on, or bidirectional mode. OE is active high. When transmitting data, set this signal to 1. When receiving data, set this signal to 0. <i>OE_SIZE</i> depends on the register mode: <ul style="list-style-type: none"> Bypass or simple register—<i>DATA_SIZE</i> = <i>SIZE</i> DDIO without half-rate logic—<i>DATA_SIZE</i> = <i>SIZE</i> DDIO with half-rate logic—<i>DATA_SIZE</i> = 2 × <i>SIZE</i> |

Table 28. Clock Interface Signals

The clock interface is an input clock interface. It consists of different signals, depending on the configuration. The GPIO IP core can have zero, one, two, or four clock inputs. Clock ports appear differently in different configurations to reflect the actual function performed by the clock signal.

| Signal Name | Direction | Description |
|-------------|-----------|--|
| ck | Input | In input and output paths, this clock feeds a packed register or DDIO if you turn off the Half Rate logic parameter. In bidirectional mode, this clock is the unique clock for the input and output paths if you turn off the Separate input/output Clocks parameter. |
| ck_fr | Input | In input and output paths, these clocks feed the full-rate and half-rate DDIOs if you turn on the Half Rate logic parameter. |
| ck_hr | | |

continued...

| Signal Name | Direction | Description |
|-------------|-----------|--|
| | | In bidirectional mode, the input and output paths use these clocks if you turn off the Separate input/output Clocks parameter. |
| ck_in | Input | In bidirectional mode, these clocks feed a packed register or DDIO in the input and output paths if you specify both these settings: <ul style="list-style-type: none"> Turn off the Half Rate logic parameter. Turn on the Separate input/output Clocks parameter. |
| ck_out | | |
| ck_fr_in | Input | In bidirectional mode, these clocks feed a full-rate and half-rate DDIOS in the input and output paths if you specify both these settings <ul style="list-style-type: none"> Turn on the Half Rate logic parameter. Turn on the Separate input/output Clocks parameter. For example, <i>ck_fr_out</i> feeds the full-rate DDIO in the output path. |
| ck_fr_out | | |
| ck_hr_in | | |
| ck_hr_out | | |
| cke | Input | Clock enable. |

Table 29. Termination Interface Signals

The termination interface connects the GPIO IP core to the I/O buffers.

| Signal Name | Direction | Description |
|---------------------------|-----------|---|
| seriesterminationcontrol | Input | Input from the termination control block (OCT) to the buffers. It sets the buffer series impedance value. |
| parallelerminationcontrol | Input | Input from the termination control block (OCT) to the buffers. It sets the buffer parallel impedance value. |

Table 30. Reset Interface Signals

The reset interface connects the GPIO IP core to the DDIOs.

| Signal Name | Direction | Description |
|-------------|-----------|--|
| sclr | Input | Synchronous clear input. Not available if you enable <i>sset</i> . |
| aclr | Input | Asynchronous clear input. Active high. Not available if you enable <i>aset</i> . |
| aset | Input | Asynchronous set input. Active high. Not available if you enable <i>aclr</i> . |
| sset | Input | Synchronous set input. Not available if you enable <i>sclr</i> . |

5.2.1. Shared Signals

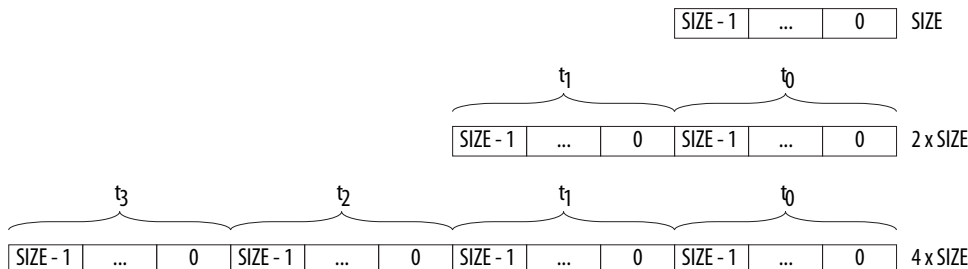
- The input, output, and OE paths share the same clear and preset signals.
- The output and OE path shares the same clock signals.



5.2.2. Data Bit-Order for Data Interface

Figure 36. Data Bit-Order Convention

This figure shows the bit-order convention for the `din`, `dout` and `oe` data signals.



- If the data bus size value is `SIZE`, the LSB is at the right-most position.
- If the data bus size value is `2 × SIZE`, the bus is made of two words of `SIZE`.
- If the data bus size value `4 × SIZE`, the bus is made of four words of `SIZE`.
- The LSB is in the right-most position of each word.
- The right-most word specifies the first word going out for output buses and the first word coming in for input buses.

Related Information

[Input Path](#) on page 43

5.2.3. Data Interface Signals and Corresponding Clocks

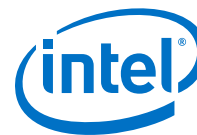
Table 31. Data Interface Signals and Corresponding Clocks

| Signal Name | Parameter Configuration | | | Clock |
|--|---|-----------|-----------------|-----------|
| | Register Mode | Half Rate | Separate Clocks | |
| din | <ul style="list-style-type: none"> • Simple Register • DDIO | Off | Off | ck |
| | DDIO | On | Off | ck_hr |
| | <ul style="list-style-type: none"> • Simple Register • DDIO | Off | On | ck_in |
| | DDIO | On | On | ck_hr_in |
| <ul style="list-style-type: none"> • dout • oe | <ul style="list-style-type: none"> • Simple Register • DDIO | Off | Off | ck |
| | DDIO | On | Off | ck_hr |
| | <ul style="list-style-type: none"> • Simple Register • DDIO | Off | On | ck_out |
| | DDIO | On | On | ck_hr_out |

continued...



| Signal Name | Parameter Configuration | | | Clock |
|---|---|-----------|-----------------|--|
| | Register Mode | Half Rate | Separate Clocks | |
| <ul style="list-style-type: none"> • sclr • sset • All pad signals | <ul style="list-style-type: none"> • Simple Register • DDIO | Off | Off | ck |
| | DDIO | On | Off | ck_fr |
| | <ul style="list-style-type: none"> • Simple Register • DDIO | Off | On | <ul style="list-style-type: none"> • Input path: ck_in • Output path: ck_out |
| | DDIO | On | On | <ul style="list-style-type: none"> • Input path: ck_fr_in • Output path: ck_fr_out |



6. Intel Stratix 10 General Purpose I/O User Guide Archives

If an IP core version is not listed, the user guide for the previous IP core version applies.

| IP Core Version | User Guide |
|-----------------|---|
| 18.0 | Intel Stratix 10 General Purpose I/O User Guide |
| 17.1 | Intel Stratix 10 General Purpose I/O User Guide |

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7. Document Revision History for Intel Stratix 10 General Purpose I/O User Guide

| Document Version | Intel Quartus Prime Version | Changes |
|------------------|-----------------------------|---|
| 2019.03.04 | 18.1 | <p>In the topics about the input path, and output and output enable paths:</p> <ul style="list-style-type: none"> Corrected the notes in the topics to specify that the GPIO Intel FPGA IP does not support dynamic calibration of bidirectional pins. Added links to the PHY Lite for Parallel Interfaces Intel FPGA IP Core User Guide: Intel Stratix 10, Intel Arria 10, and Intel Cyclone 10 GX Devices for more information about applications that require dynamic calibration for bidirectional pins. |
| 2019.01.23 | 18.1 | Updated the Intel Quartus Prime version of the document. |
| 2019.01.14 | 18.1 | <ul style="list-style-type: none"> Removed statement that says that the programmable V_{OD} value of "0" is not available for the LVDS I/O standard. In the topic about dynamic OCT, added link to PHY Lite for Parallel Interfaces Intel FPGA IP Core User Guide: Intel Stratix 10, Intel Arria 10, and Intel Cyclone 10 GX Devices for applications that require dynamic OCT for bidirectional pins. |
| 2018.07.09 | 18.0 | <ul style="list-style-type: none"> Added 24 mA and 20 mA current strength settings for the 3.0 V LVTTTL I/O standard. Added Differential SSTL-15 Class I and Class II, and Differential SSTL-18 Class I and Class II to the table that lists the programmable current strengths. Added Differential SSTL-15 Class I and Class II to the tables that list the R_S OCT with calibration and R_S OCT without calibration. Removed 50 Ω R_T OCT for SSTL-15 and Differential SSTL-15 I/O standards. Added a note about not pulling the output voltage higher than the V_i (DC) level in the topic about the programmable open drain output. |
| 2018.05.10 | 18.0 | <ul style="list-style-type: none"> Updated a footnote related to 3 V I/O to specify that the 3 V I/O is not supported in the E-Tile transceiver tiles. Added a footnote to the I/O standards support table to specify that a transceiver tile's 3 V I/O bank is not available when the tile is powered down. Removed DDR2 support. Removed the topic about MultiVolt I/O interface and added the information to the topic about I/O standards voltage support. Moved the I/O count tables and I/O banks location figures to the pin-out files. Updated the figure titles in the topic about LVPECL termination to clarify that the figures refer to external termination. There is no OCT support for LVPECL I/O standard. Clarified that to utilize the I/O registers when implementing DDR circuitry, use the GPIO Intel FPGA IP in <i>I/O Buffer and Registers in Intel Arria 10 Devices</i>. Clarified that all singled-ended I/O configured to 3 V I/O bank supports all programmable I/O elements except programmable pre-emphasis, R_D on-chip termination (OCT), calibrated R_S and R_T OCT, and internal V_{REF} generation. |

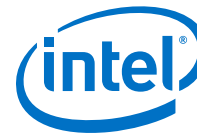
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7. Document Revision History for Intel Stratix 10 General Purpose I/O User Guide

UG-S10GPIO | 2019.03.04



| Document Version | Intel Quartus Prime Version | Changes |
|------------------|-----------------------------|--|
| | | <ul style="list-style-type: none"> Clarified that 3 V I/O bank supports single-ended and differential SSTL, HSTL, and HSUL I/O standards. Specified that VREF pins are dedicated for voltage-reference signal-ended I/O standards in Guideline: VREF Sources and VREF Pins on page 37. Clarified the type of I/O buffers available in Intel Arria 10 FPGA devices and Intel Arria 10 SoC devices in I/O Standards and Voltage Levels in Intel Stratix 10 Devices on page 7. Changed <i>logic-to-pin</i> to <i>logic to the output buffer</i> in <i>Programmable Open-Drain Output</i> section. Renamed the IP core from "Intel FPGA GPIO" to "GPIO Intel FPGA IP". Corrected instances of "clk_fr" and "clk_hr" to "ck_fr" and "ck_hr". Updated the GPIO IP core input path and output paths diagrams to show the actual IP core signal names. Updated the table listing the reset interface signals to improve clarity. |

| Date | Version | Changes |
|---------------|------------|--|
| November 2017 | 2017.11.06 | <ul style="list-style-type: none"> Clarified that each 3 V I/O bank supports only two OEs for its eight single-ended I/Os. Removed Intel Stratix 10 TX 4500 and TX 5500 devices. Added package SF48 to Intel Stratix 10 TX 1650 and TX 2100 devices. Added Intel Stratix 10 MX devices. Specified that 3 V I/Os are not available for Intel Stratix 10 devices with E-Tile transceiver variants. Updated descriptions of the table that lists the GPIO buffers and LVDS channels in Intel Stratix 10 GX devices to specify that the LVDS channels counts include dedicated clock pins. Removed the HF50 package from all Intel Stratix 10 devices. Restructured the topics and tables that list the I/O banks locations and pin counts. Added support for 2.5 V LVCMOS I/O standard. Added 3 V I/O bank support for the 1.8 V LVCMOS, 1.5 V LVCMOS, and 1.2 V LVCMOS I/O standards. Removed all instances of "DDR3U". Intel validates and support only IPs for memory interfaces listed in Performance Support Summary, Intel Stratix 10 External Memory Interfaces User Guide. Added a note to specify that to use the 1.2 V, 1.5 V, 1.8 V, and 2.5 V I/O standards on the 3 V I/O bank, you need to set the USE_AS_3V_GPIO assignment. Updated the tables that lists the programmable IOE features supported by the I/O buffer types and I/O standards. Removed the table that lists the I/O standards and current strengths that support programmable slew rate control. Added information about the default slew rate setting. Updated the topic about programmable IOE delay to remove the input and output delay information. The I/O delay numbers are pending characterization. Added information about the default predefined current strength if you do not specifically assign a current strength in the Intel Quartus Prime software. |

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| Date | Version | Changes |
|----------------|------------|---|
| | | <ul style="list-style-type: none"> • Updated the table listing the programmable current strength settings. <ul style="list-style-type: none"> – Added current strength settings for these I/O standards: <ul style="list-style-type: none"> • 2.5 V LVCMOS • SSTL-135 and Differential SSTL-135 • SSTL-125 and Differential SSTL-125 • SSTL-12 and Differential SSTL-12 Class I • POD12 and Differential POD12 • Differential 1.8 V HSTL Class I and Class II • Differential 1.5 V HSTL Class I and Class II • Differential 1.2 V HSTL Class I – Removed 6 mA, 4 mA, and 2 mA HPS current strength settings for the 1.8 V LVCMOS I/O standard – Removed all HPS current strength settings except for the 1.8 V LVCMOS I/O standard – Removed 12 mA and 10 mA current strength settings from the following I/O standards: <ul style="list-style-type: none"> • 1.2 V LVCMOS • SSTL-18 Class I • SSTL-15 Class I • 1.2 V HSTL Class I – Removed 16 mA current strength settings from the SSTL-18 Class II and SSTL-15 Class II I/O standards – Updated the current strength setting from 16 mA to 14 mA for the 1.8 V HSTL Class II and 1.5 V HSTL Class II I/O standards – Removed programmable current strength for the 1.2 V HSTL Class II I/O standard • Removed OCT support for 3 V I/O. • Updated the tables listing the R_S and R_T OCT support to update I/O standards and available OCT settings. • Updated the tables listing the external termination schemes to add 2.5 V LVCMOS. • Updated the signal names in figures to match the signal names in the Intel FPGA GPIO IP core. • Added the output path waveform. • Renamed "Altera GPIO IP core" to "Intel FPGA GPIO IP core". • Clarified that the A_{SET} and A_{CLR} signals are active high. |
| September 2017 | 2017.09.04 | <ul style="list-style-type: none"> • Added 8 mA to SSTL-2 Class II, SSTL-18 Class II, and SSTL-15 Class II, and removed 12 mA from SSTL-18 Class II in the list of current strength settings that support programmable output slew rate control. • Added 8 mA current strength settings to SSTL-18 Class II and SSTL-15 Class II. • Added these I/O standards to the table listing the selectable I/O standards for R_S OCT without calibration: <ul style="list-style-type: none"> – Differential SSTL-15 – Differential SSTL-135 – Differential SSTL-125 – Differential SSTL-12 – Differential HSUL-12 • Added 16 mA current strength setting to 1.8 V LVCMOS I/O standard. • Added 12 mA and 10 mA current strength settings to 1.2 V LVCMOS I/O standard. • Removed 25 Ω and 50 Ω R_S OCT settings from Differential SSTL-15 in the table that lists the selectable I/O standards for R_S OCT with calibration. • Updated the table listing the Altera GPIO buffer parameters to specify the conditions for the Use bus-hold circuitry parameter option. |

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7. Document Revision History for Intel Stratix 10 General Purpose I/O User Guide
UG-S10GPIO | 2019.03.04



| Date | Version | Changes |
|---------------|------------|---|
| February 2017 | 2017.02.13 | <ul style="list-style-type: none">Removed the SF48 package from the Intel Stratix 10 TX 1650 and TX 2100 devices.Updated topics to clarify that the 3 V I/O banks do not have I/O registers and DDIOs, and do not support all features of the Altera GPIO IP core. |
| December 2016 | 2016.12.05 | Corrected the number of I/Os in I/O bank 3L for the HF55 package of the GX 4500 and SX 5500 devices. |
| October 2016 | 2016.10.31 | Initial release. |